

# Energy efficient A/D converter design

Akira Matsuzawa

Tokyo Institute of Technology

2011.06.18

A. Matsuzawa, Titech



# Outline

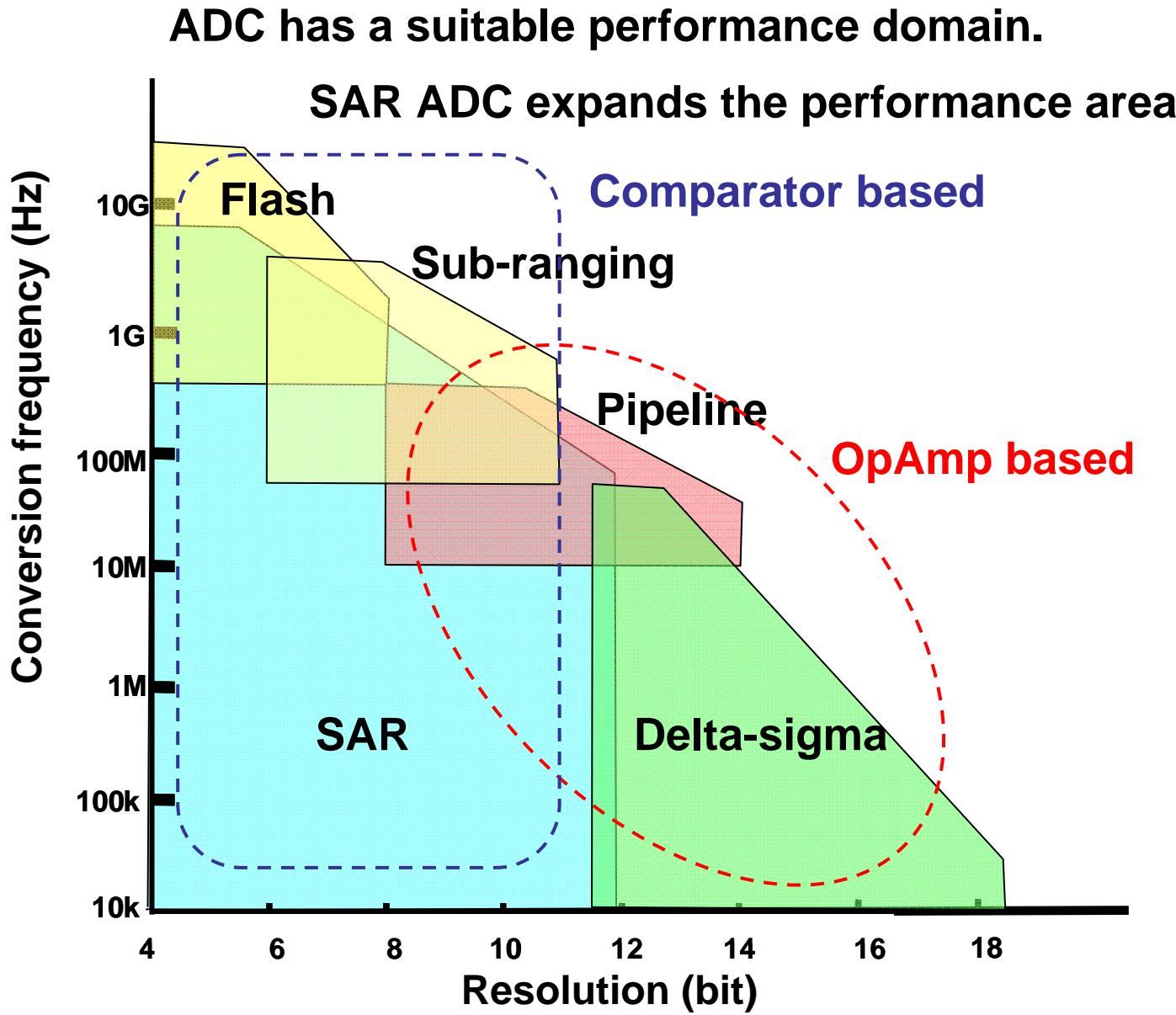
---

2

- **Overview of ADCs**
- **OpAmp based ADC design**
- **Comparator based ADC design : SAR ADCs**
- **Flash and sub-ranging ADCs**
- **Summary**

# Performance and architectures of ADCs

3



# Strategy of energy efficient ADC design

4

## Reducing static power

Resistor DAC → Capacitor DAC

OpAmp based → Dynamic comparator based

## Reducing capacitance

$$E_d \approx CV_{DD}^2$$

# of CMP Flash → Sub-range → SAR

$$\Delta V_T \propto \frac{1}{\sqrt{C_G}}$$

TR size Large TR → Small TR with compensation

$$\overline{V_n} \propto \frac{1}{\sqrt{C}}$$

Noise Use complementally ckt.

Clock Use self clocking

## Reducing voltage

Effective to digital gates

Use forward or adaptive body biasing

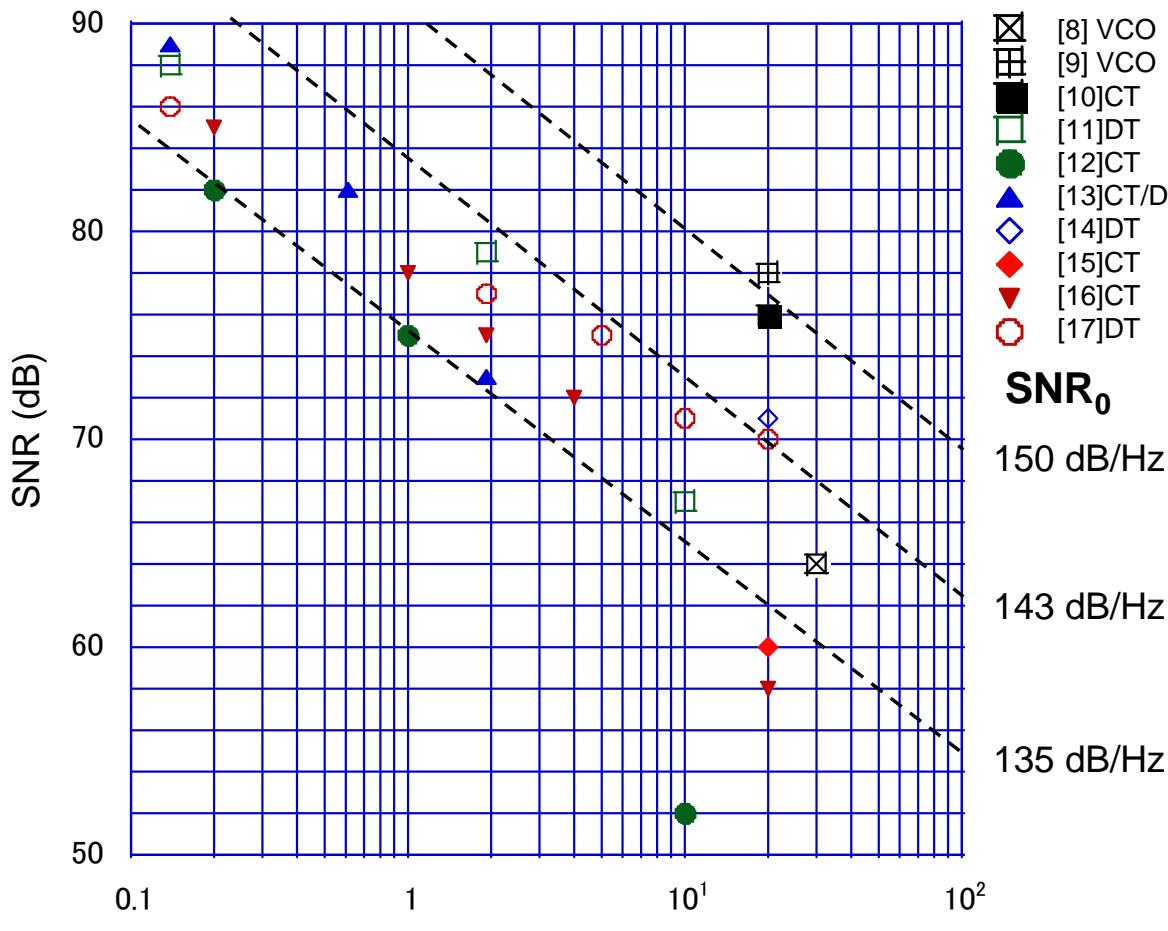
# SNR vs. signal bandwidth

5

**SNR of ADCs is inversely proportional to signal bandwidth,  $f_b$ .**

→ Higher bandwidth results in lower SNR and effective resolution.

$$SNR(dB) \approx SNR_0(dB) - 10 \log f_b$$



$$SNR(dB) = 10 \log \left( \frac{P_s}{P_N} \right)$$

$$P_N = P'_N (\text{spectrum density}) \times f_b$$

$$SNR(dB) = 10 \log \left( \frac{P_s}{P'_N} \right) - 10 \log f_b$$

$$SNR(dB) = SNR_0(dB) - 10 \log f_b$$

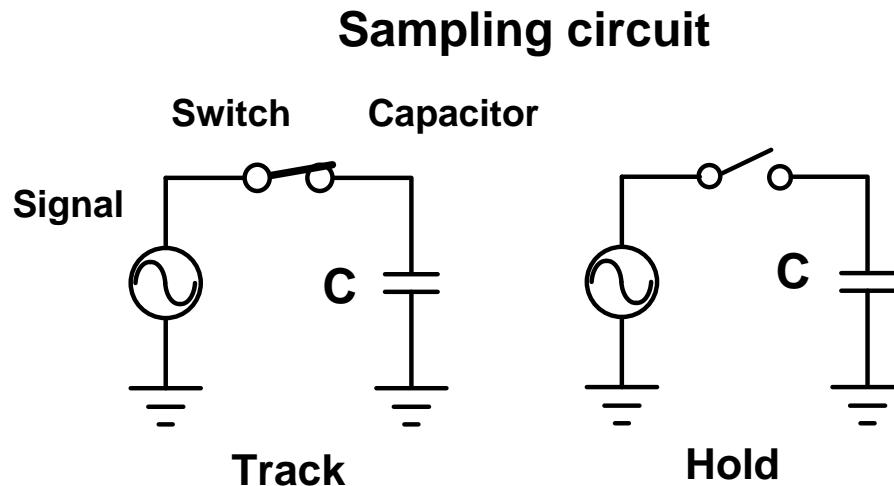
# Fundamental power of sampling circuit

6

Fundamental power of sampling is often used.

$$P_s = 24kTf_s 2^{2N}$$

However this neglects power for comparison.



**Quantization voltage**

$$V_{qn} = \frac{V_{FS}}{2^N}$$

**Quantization noise power**

$$P_{qn} = \frac{V_{qn}^2}{12} = \frac{V_{FS}^2}{12 \cdot 2^{2N}}$$

**Noise balance**

$$V_n^2 = P_{qn}$$

**Capacitance**

$$C = 12kT \frac{2^{2N}}{V_{FS}^2}$$

**P<sub>d</sub> of sampling circuit**

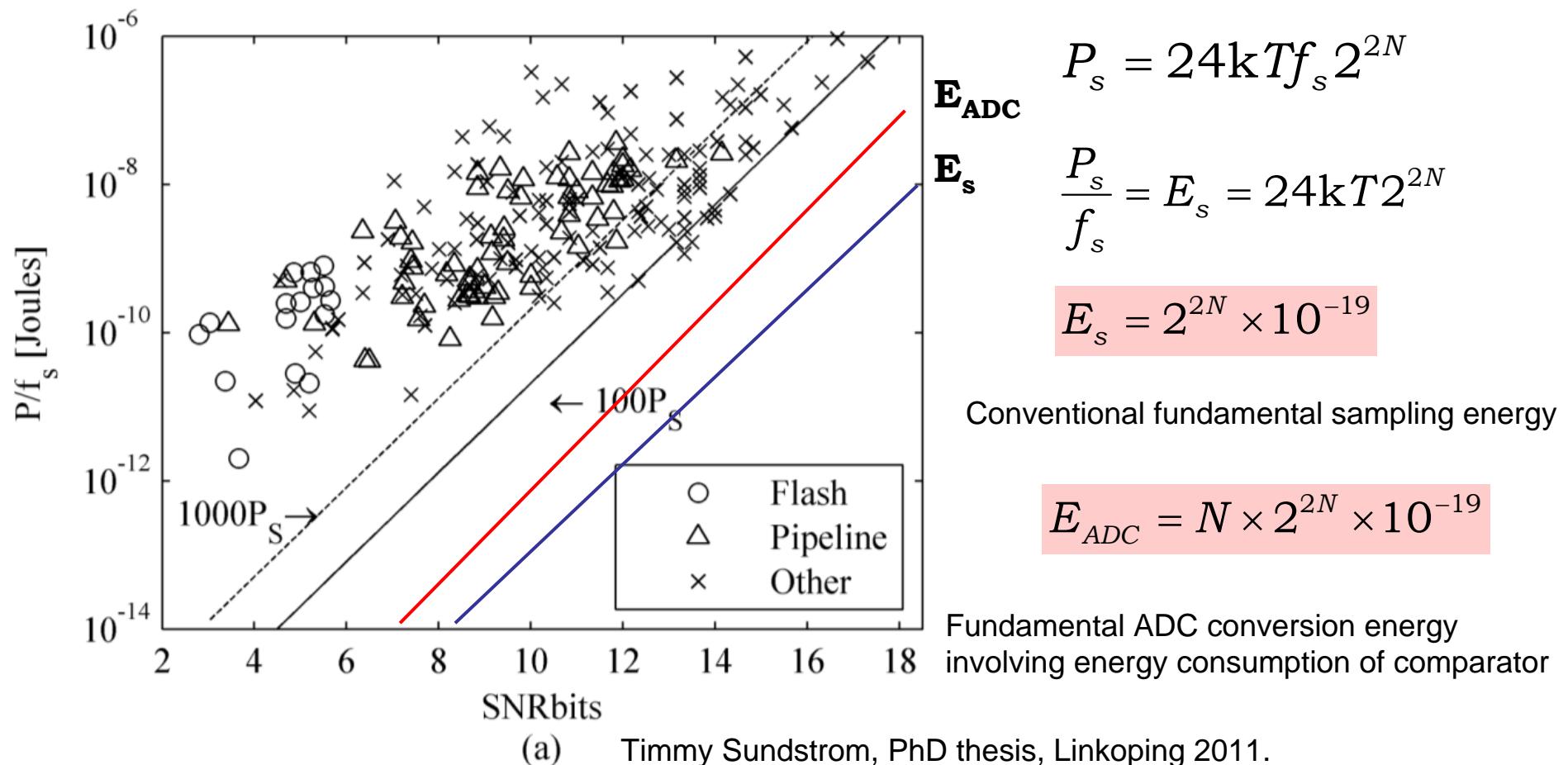
$$P_d = 2f_s C V_{FS}^2 = 24kTf_s 2^{2N}$$

# Energy consumption of ADC

7

Consumed energy of ADC is mainly determined by the resolution.

Energy of ADC is reaching 100x of the fundamental sampling energy, and **10x** of the fundamental ADC energy consumption.



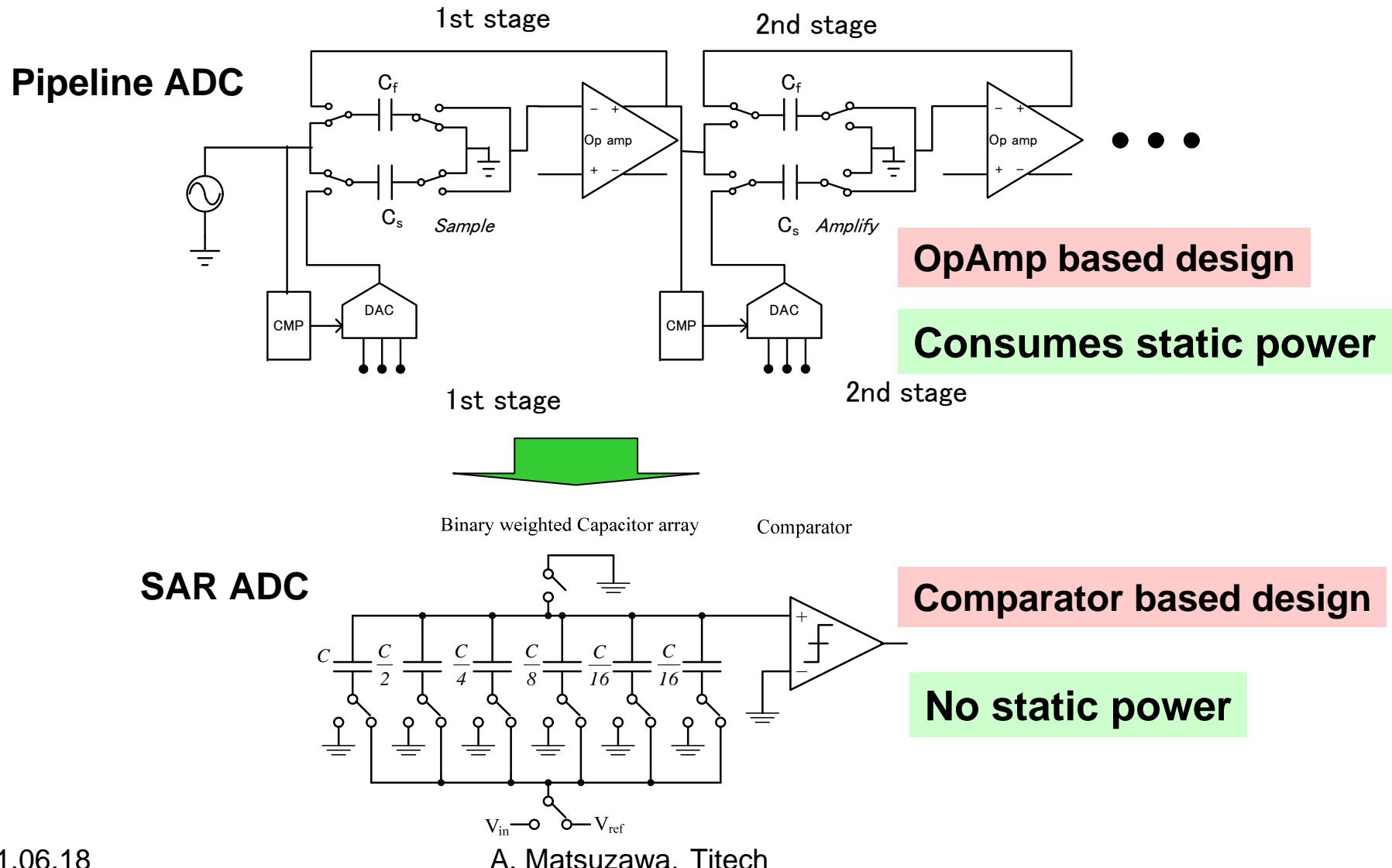
---

# OpAmp based ADC design

# Mega-technology trend of ADCs

9

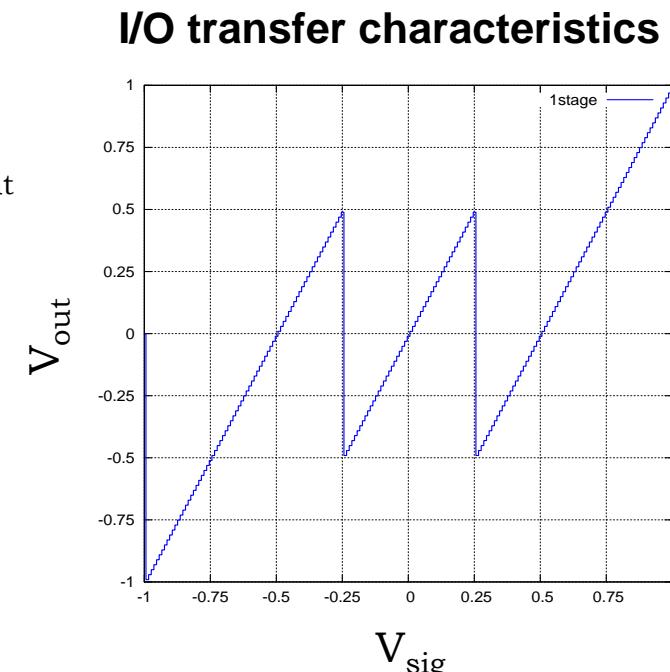
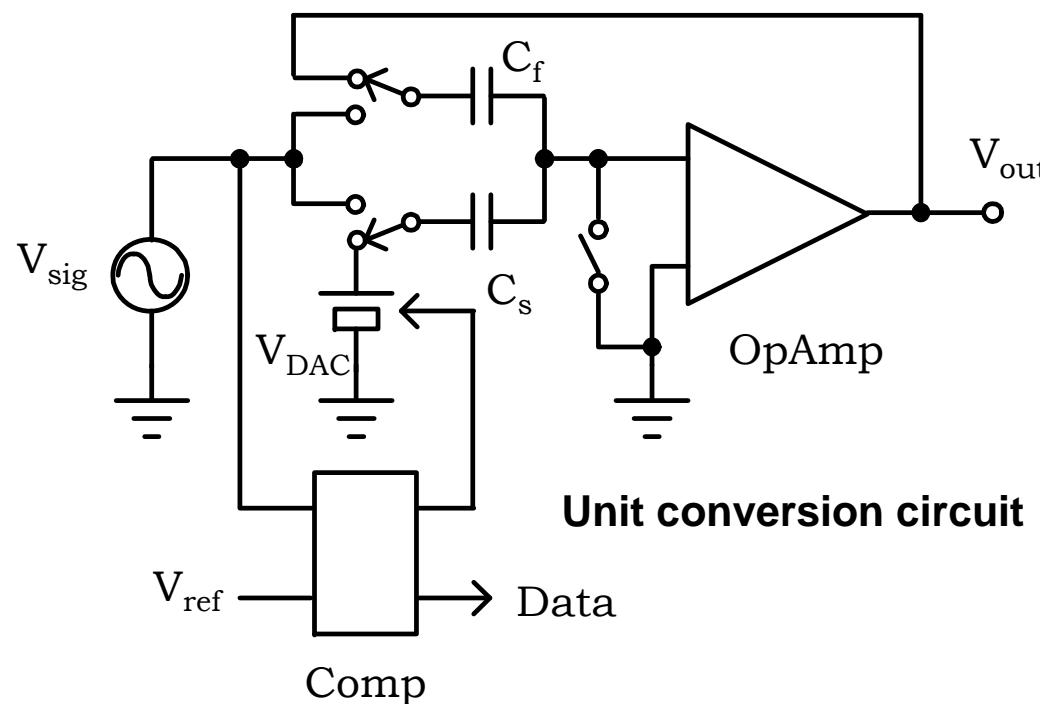
Major conversion scheme is now changing from pipeline to SAR.



# Amplifier for pipeline ADC

10

An OpAmp realizes an accurate voltage amplification.



$$V_{out} \approx V_{sig} \left( 1 + \frac{C_s}{C_f} \right) - \frac{C_s}{C_f} V_{DAC} \approx 2 \left( V_{sig} - \frac{V_{DAC}}{2} \right)$$

$$V_{DAC} = \pm V_{ref}, 0$$

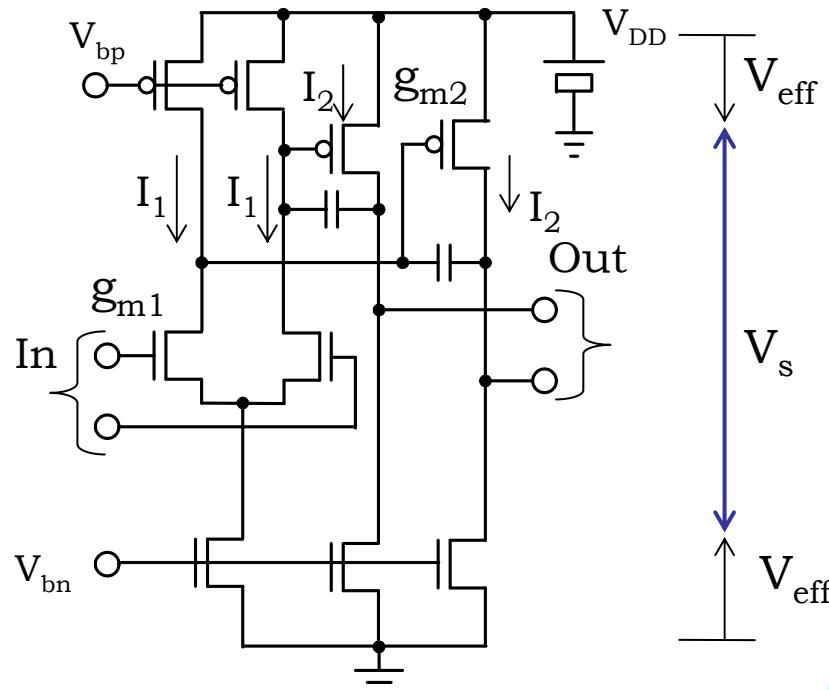
Conventionally  $C_s = C_f = C_0$

# Low voltage OpAmp: Headroom and Pd

11

A two stage cascade OpAmp can realize low voltage operation.  
However, the output voltage swing become lower at low voltage operation.

$$V_{s\_pp} = 2(V_{DD} - 2V_{eff})$$



Two stage OpAmp

$$GBW \approx \frac{g_{m2}}{4\pi C_0} = Nf_c$$

$$V_{eff} \equiv V_{GS} - V_T$$

$$V_{eff} \approx 0.15V$$

$$\therefore g_{m2} = \frac{2I_2}{V_{eff}} = 4\pi C_0 Nf_c$$

$$C_0 \geq \left(2 + \frac{\gamma n}{\beta}\right) \frac{kT}{V_{n\_th}^2}$$

$$\therefore I_2 = 2\pi C_0 Nf_c V_{eff} = \frac{2\pi Nf_c V_{eff} kT}{V_{n\_th}^2} \left(2 + \frac{\gamma n}{\beta}\right)$$

$$g_{m2} = 4g_{m1} \quad \therefore I_2 = 4I_1$$

$$I_{tot} = \frac{5}{2} I_2$$

$$n=4$$

$$P_{da} = V_{DD} \cdot I_{tot} = 5\pi V_{DD} \frac{Nf_c V_{eff} kT}{V_{n\_th}^2} \left(2 + \frac{\gamma n}{\beta}\right)$$

## Total Pd of ADC

$$P_{dpipe} = 2P_{damp} = 10\pi V_{DD} \frac{Nf_c V_{eff} kT}{V_{n\_th}^2} \left(2 + \frac{\gamma n}{\beta}\right)$$

# Required performances

12

**Required gain and bandwidth of OpAmp and capacitance are determined by the resolution and conversion frequency.**

<b>Open loop gain</b>	$G_{(dB)} > 6N + 10$	70dB: 10b 94dB: 14b	N: Resolution $f_c$ : Conversion freq.
-----------------------	----------------------	------------------------	---

**Quantization voltage**  $\overline{V_q^2} = \frac{1}{3} \left( \frac{V_{sig}}{2^N} \right)^2 = \frac{1}{3} \left( \frac{V_{DD} - 2V_{eff}}{2^N} \right)^2$  ENOB: Effective # of bit

**Thermal noise**       $V_{n\_th}^2 = \overline{V_q^2} \left( 2^{2\Delta ENOB} - 1 \right)$      $\Delta ENOB$  : Degradation from ideal

<b>Unit capacitance</b>	$C_0 > \left(2 + \frac{\gamma n}{\beta}\right) \frac{kT}{V_{n\_th}^2}$	$\gamma$ : noise coefficient $t \approx 2$ $n$ : # of noise sources $\beta$ : feedback factor $\approx \frac{1}{3}$
-------------------------	--	---

$$\mathbf{GBW} \quad GBW > Nf_c$$

# $C_0$ and $P_d$ at low voltage operation

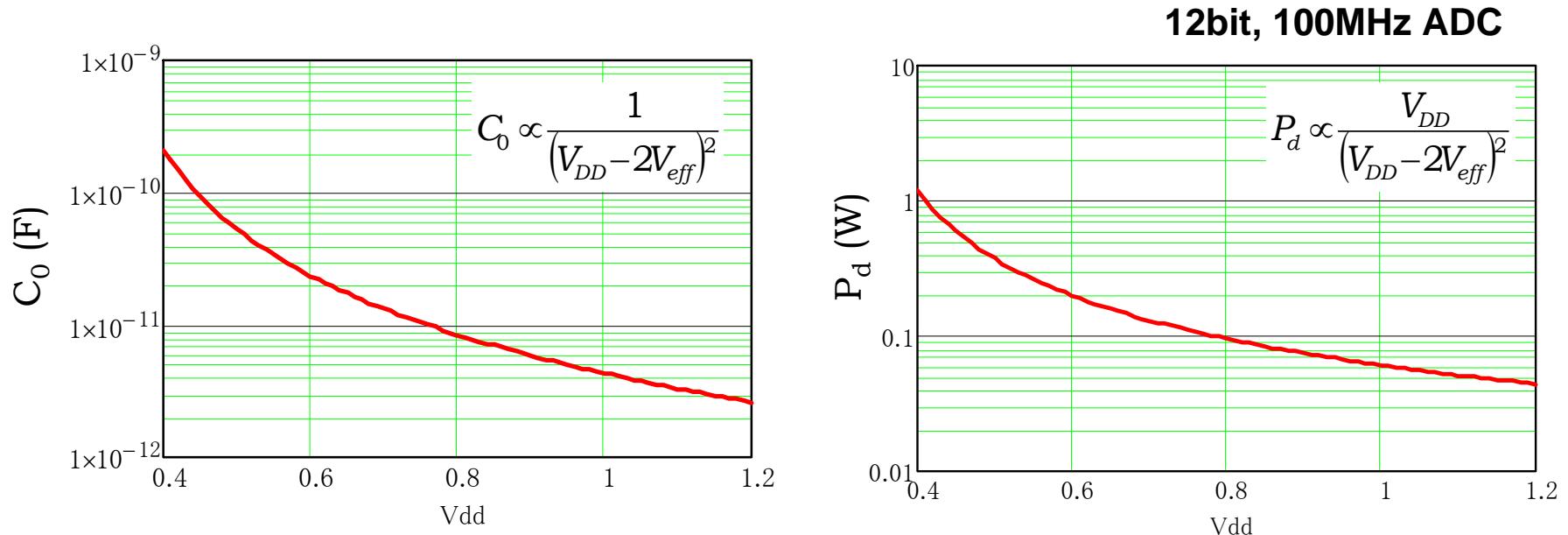
13

Capacitance should be larger at low voltage operation to keep sufficient SNR.  
This results in rapid increase of power dissipation.

Low voltage doesn't make sense for pipeline ADC.

$$V_{s\_pp} = 2(V_{DD} - 2V_{eff}) \quad SNR \propto \frac{C_0 V_{s\_pp}^2}{kT} \approx \frac{2C_0 (V_{DD} - 2V_{eff})^2}{kT} \quad C_0 \propto \frac{kT \cdot SNR}{(V_{DD} - 2V_{eff})^2}$$

$$f_c \propto GBW \propto \frac{g_m}{C_0} \approx \frac{2I_D}{C_0 V_{eff}} \quad P_d = I_D V_{DD} \propto C_0 f_c V_{eff} V_{DD} \propto \frac{f_c \cdot T \cdot SNR V_{eff} V_{DD}}{(V_{DD} - 2V_{eff})^2}$$



# FoM: Figure of Merit of ADC

14

**FoM stands for consumed energy normalized by the effective steps.**

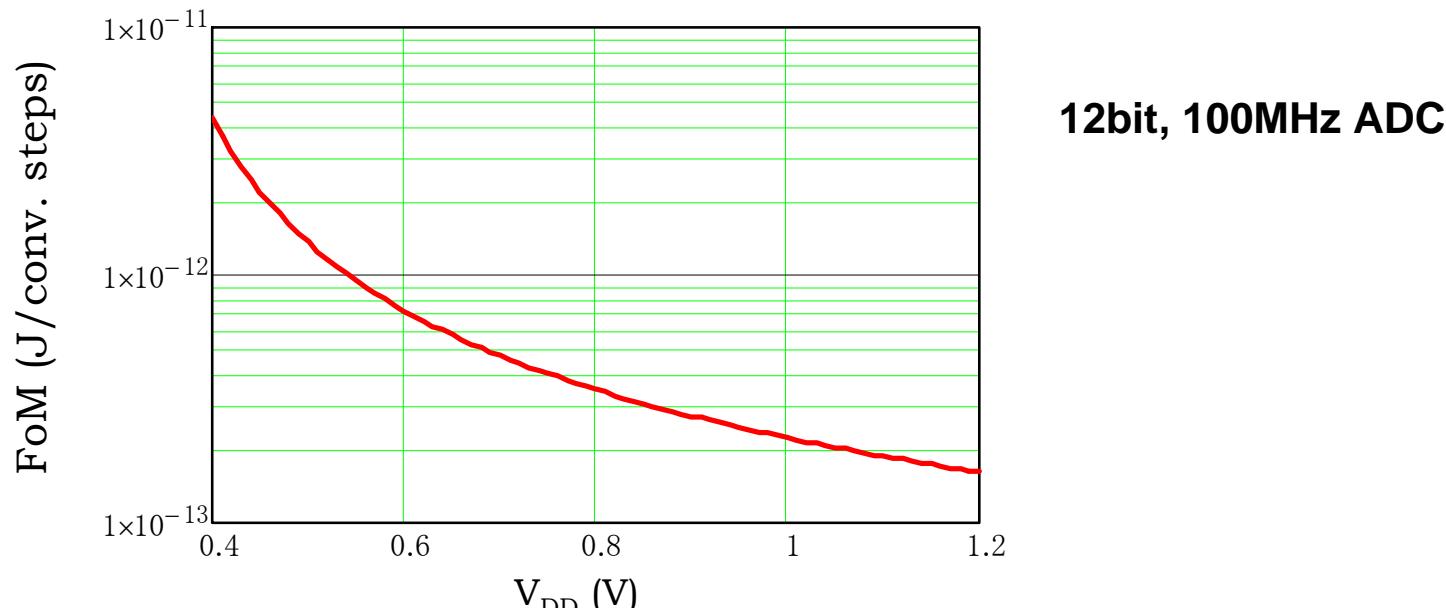
**Low voltage operation for OpAmp based ADC increases FoM.**

$$FoM(J) = \frac{P_d}{f_c \times 2^{\Delta ENOB}} = \frac{P_d \times 2^{\Delta ENOB}}{f_c \times 2^N}$$

$$P_d = 30\pi N f_c \left( 2 + \frac{n\gamma}{\beta} \right) kT \left( \frac{2^{2N}}{2^{2\Delta ENOB} - 1} \right) V_{eff} \frac{V_{DD}}{(V_{DD} - 2V_{eff})^2}$$

$$FoM = 30\pi \left( 2 + \frac{n\gamma}{\beta} \right) kT \left( \frac{2^{\Delta ENOB}}{2^{2\Delta ENOB} - 1} \right) V_{eff} \frac{V_{DD}}{(V_{DD} - 2V_{eff})^2}$$

$\Delta ENOB$ : Degradation from ideal



---

# **Comparator based ADC design : SAR ADC**

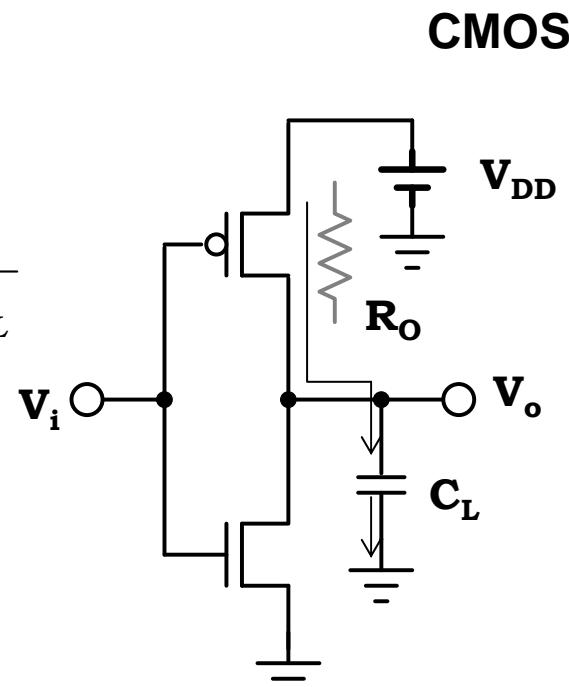
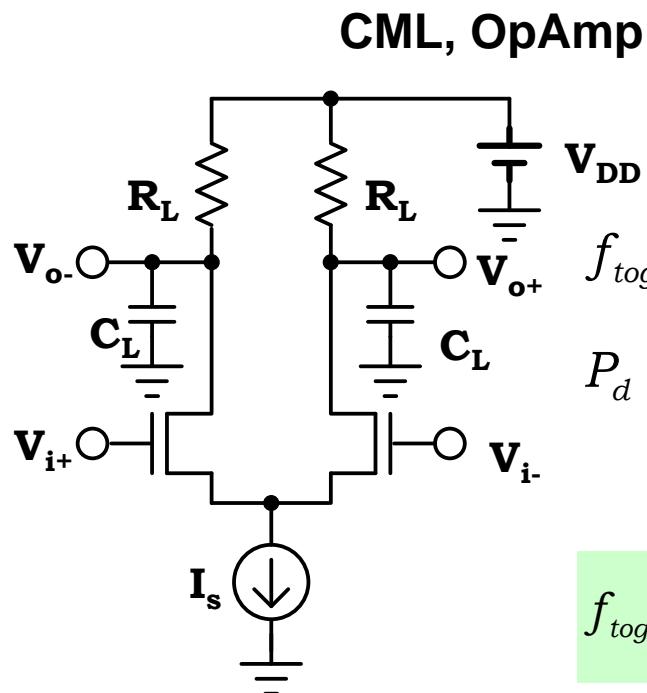
# Basic idea for low energy analog design

16

Conventional analog circuits consume larger energy.

Dynamic circuits doesn't consume larger energy.

CMOS: Consumed energy is **independent** of delay time.

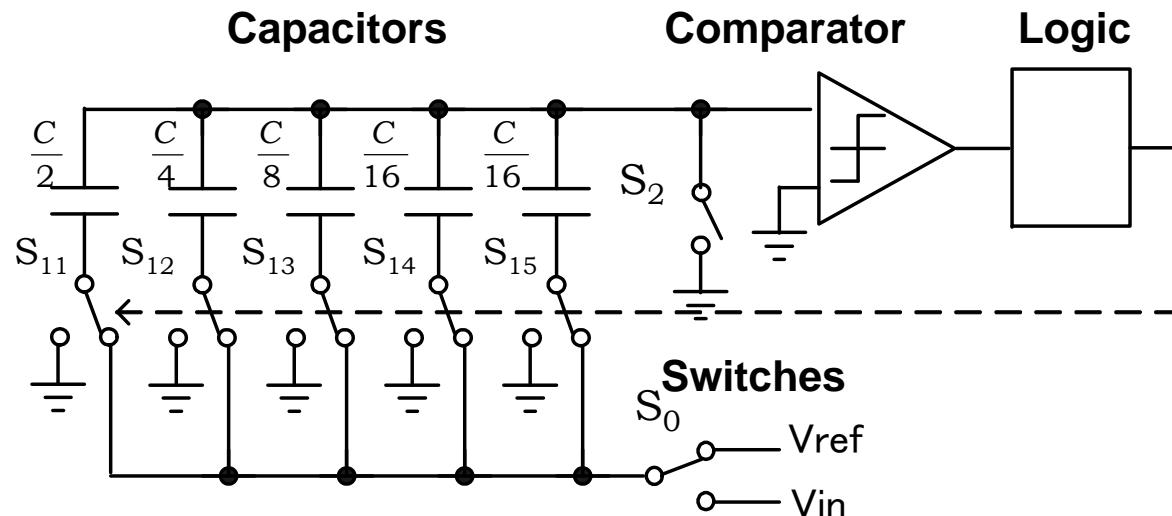


# SAR ADC

17

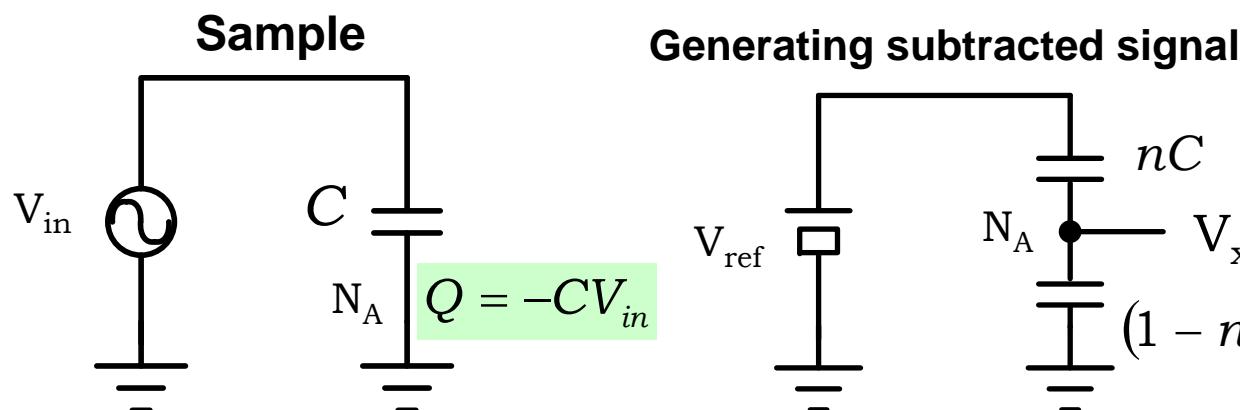
**SAR can be designed to consume no static power.**

**SAR can realize larger signal swing compared with pipeline ADC.**



**Not OpAmp based,  
but comparator based**

**No resistors  
No static current !  
Potentially full swing**



$$E \approx \frac{1}{2} CV_{ref}^2$$

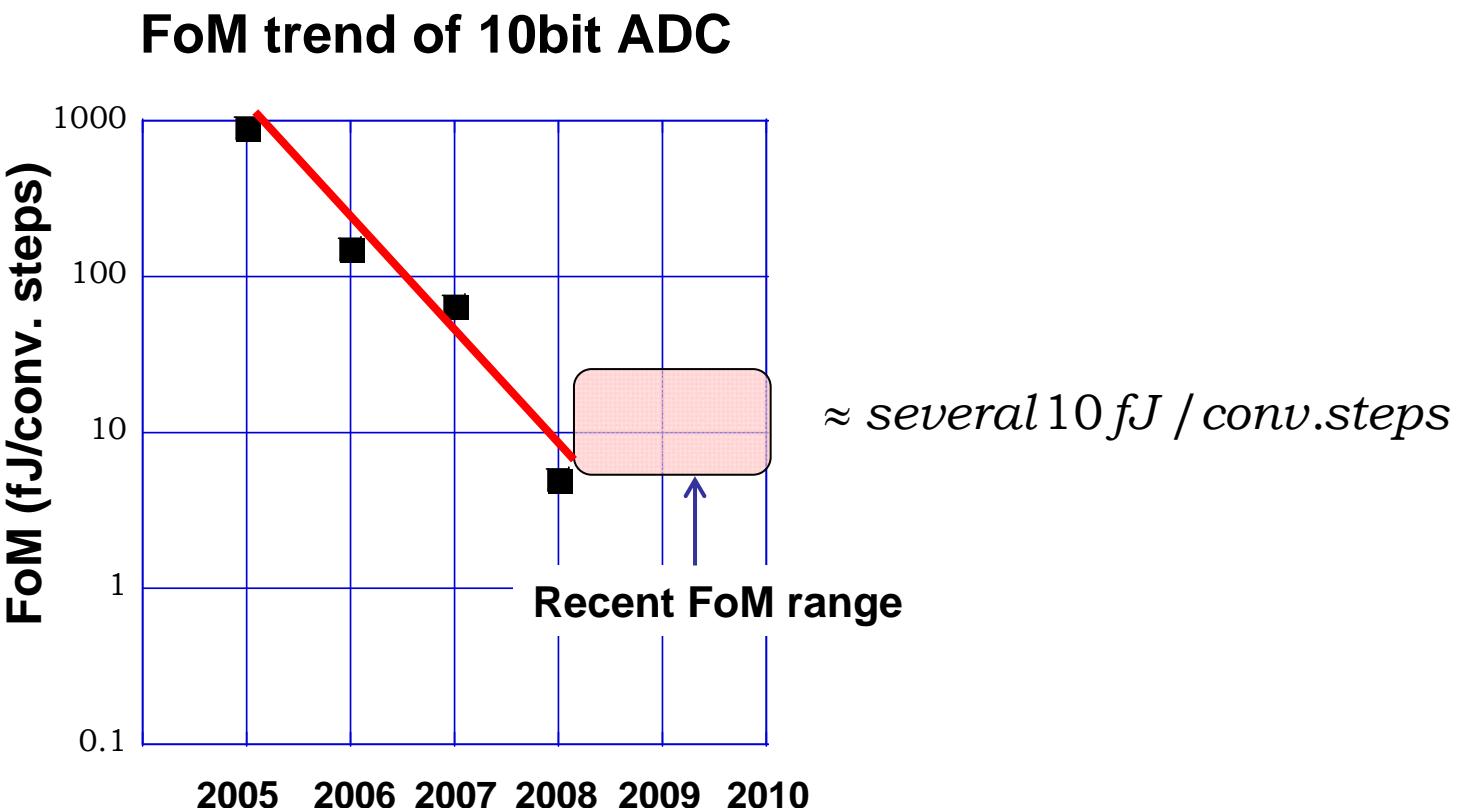
$$V_x = -(V_{sig} - n \cdot V_{ref}) \quad 0 < n < 1$$

# Performance overview of SAR ADCs

18

FoM has lowered rapidly due to the progress of SAR ADC.

1/200 during three years.

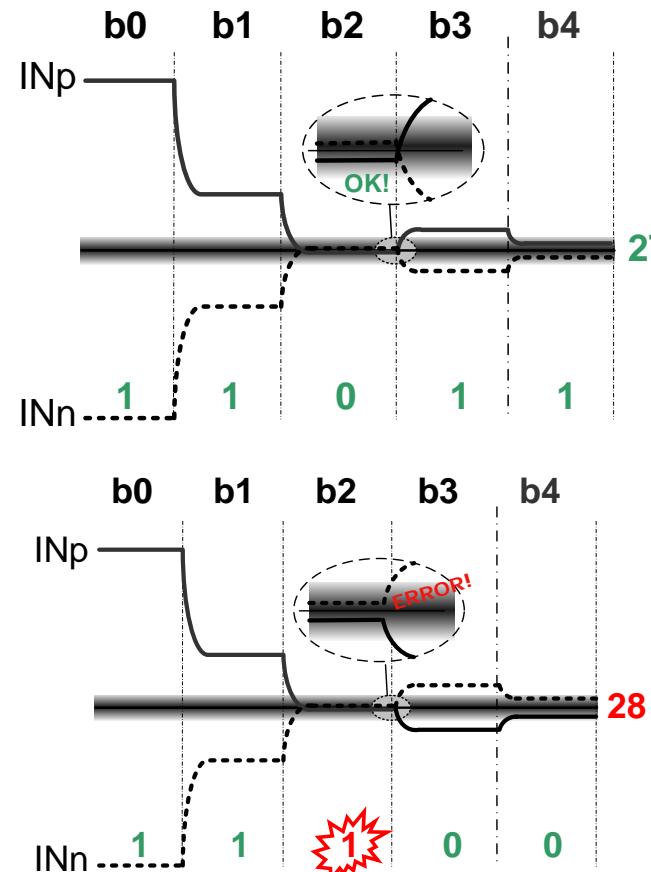
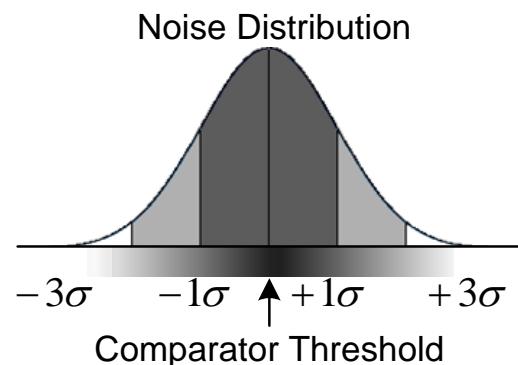
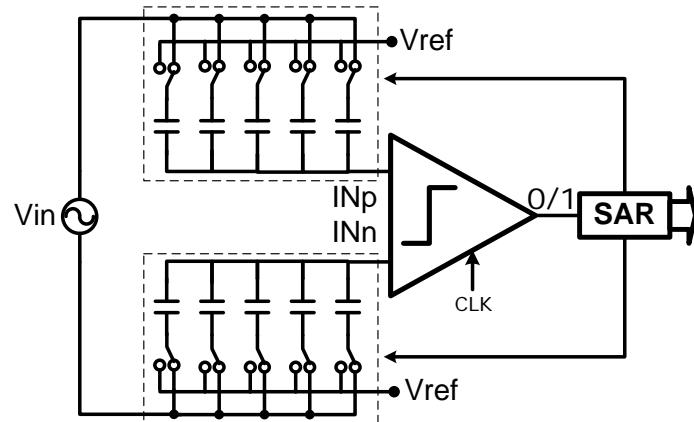


# Issue of comparator for SAR ADCs

19

A comparator has noise and this results in conversion error.

5b Charge Redistribution (CR) SAR ADC



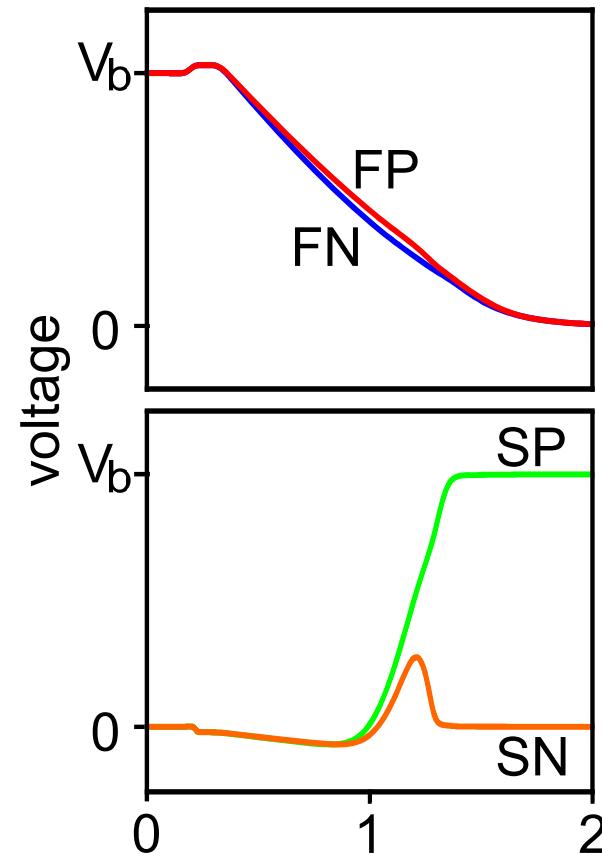
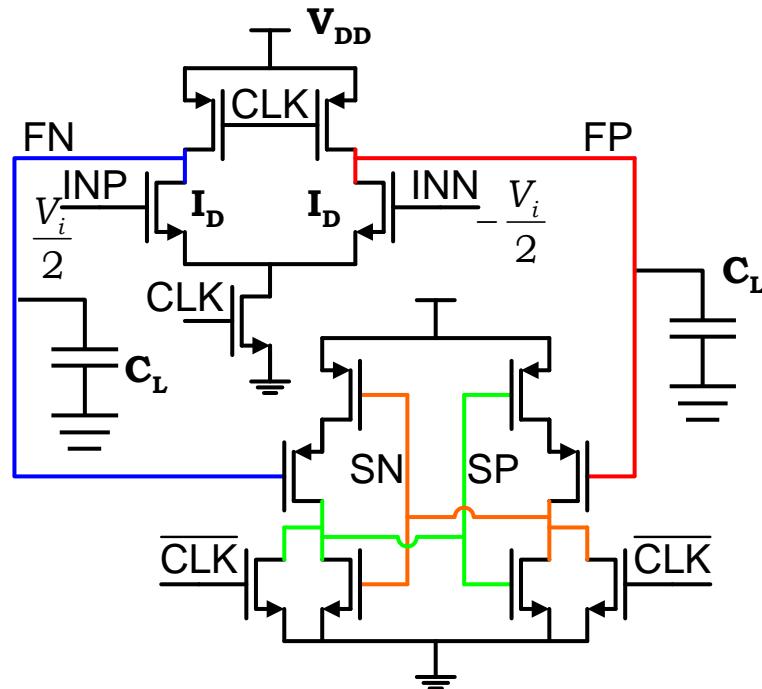
V. Giannini, P. Nuzzo, V. Chironi, A. Baschirotto, G. van der Plas, and J. Craninckx, "An 820uW 9b 40MS/s Noise Tolerant Dynamic-SAR ADC in 90nm Digital CMOS," IEEE ISSCC 2008, Dig. of Tech. Papers, pp.238-239, Feb. 2008.

# Dynamic comparator

20

A dynamic comparator is widely used to reduce static power.

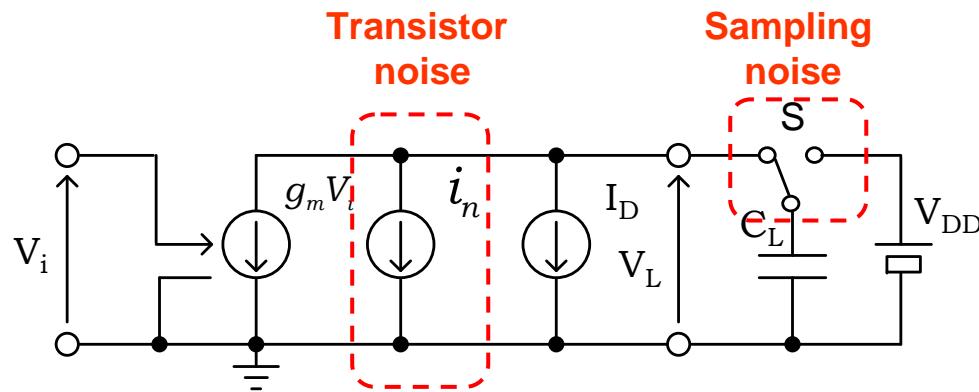
The difference in input voltages causes a difference in discharging speed.



D. Schinkel, E. Mensink, E. Klumperink, Ed Van Tuijl, B. Nauta,  
“A Double-Tail Latch-Type Voltage Sense Amplifier with 18ps  
Setup-Hold Time,” ISSCC Dig. of Tech. Papers, pp.314-315, Feb.,  
2007.

# Deriving noise equation

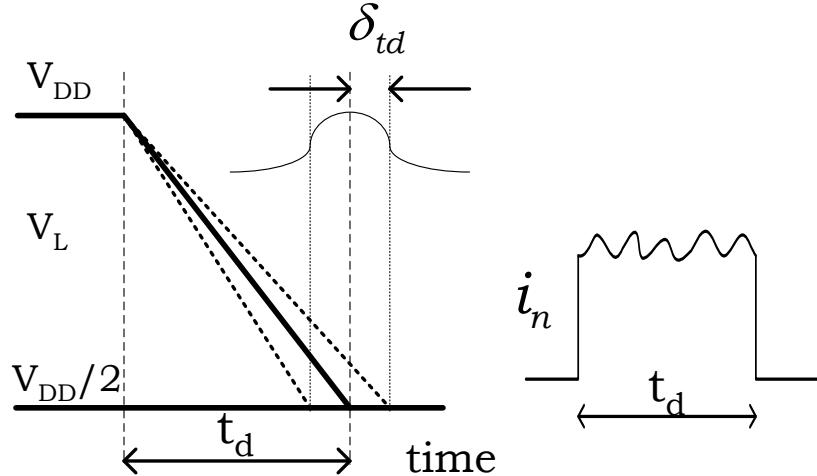
21



**Transistor noise**

**Sampling noise**

**Equivalent circuit**



**Voltage and timing**

**TR noise**

## 1) Sampling noise of Switch

$$\langle v_n^2 \rangle = \frac{kT}{C_L}, \quad \delta_{t_d}^2 = \frac{\langle v_n^2 \rangle}{\left( \frac{I_D}{C_L} \right)^2} = \frac{kTC_L}{I_D^2}$$

## 2) Transistor noise

$$\delta t = \frac{C_L}{I_D} \delta v \quad \text{Noise voltage of output by current noise}$$

$$v_n = \frac{1}{C_L} \int_0^{t_d} i_n dt \quad \delta_{t_d}^2 = \frac{C_L^2}{I_D^2} \delta_{vn}^2 = \frac{1}{I_D^2} \left\langle \left( \int_0^{t_d} i_n dt \right)^2 \right\rangle$$

$$\delta_{t_d}^2 = \frac{kTC_L}{I_{ds}^2} \left( \alpha \gamma \frac{V_{dd}}{V_{eff}} + 1 \right)$$

$$\delta V_{in}^2 = \left( \frac{V_{eff}}{a} \frac{\delta_{td}}{t_d} \right)^2 = \frac{4kTV_{eff}^2}{a^2 C_L V_{dd}^2} \left( \alpha \gamma \frac{V_{dd}}{V_{eff}} + 1 \right)$$

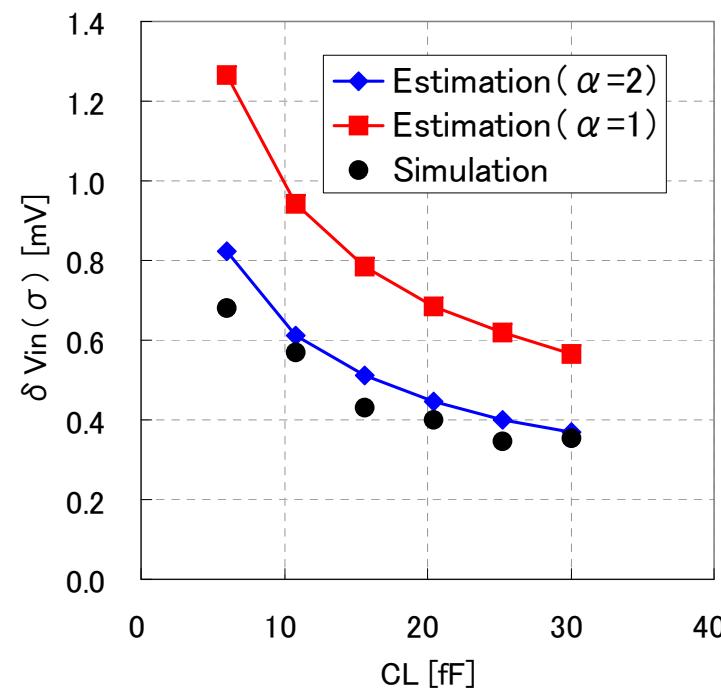
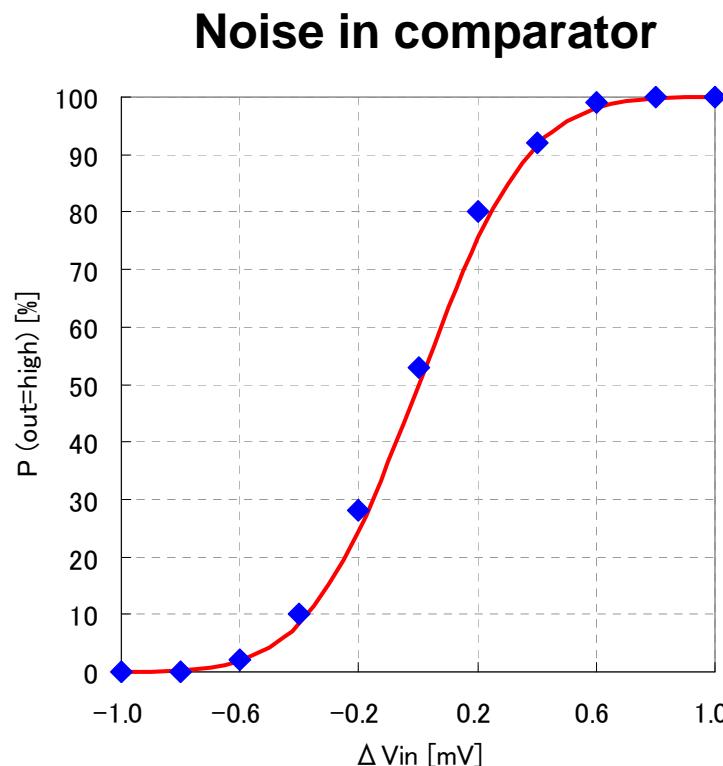
A. Matsuzawa," IEEE 8th International Conference on ASIC(ASICON), pp. 218-221, Oct. 2009.

# Match with noise simulation

22

The derived equation has a good match with simulation.

$$\delta V_{in}^2 = \frac{4kTV_{eff}^2}{\alpha^2 C_L V_{dd}^2} \left( \alpha \gamma \frac{V_{dd}}{V_{eff}} + 1 \right)$$



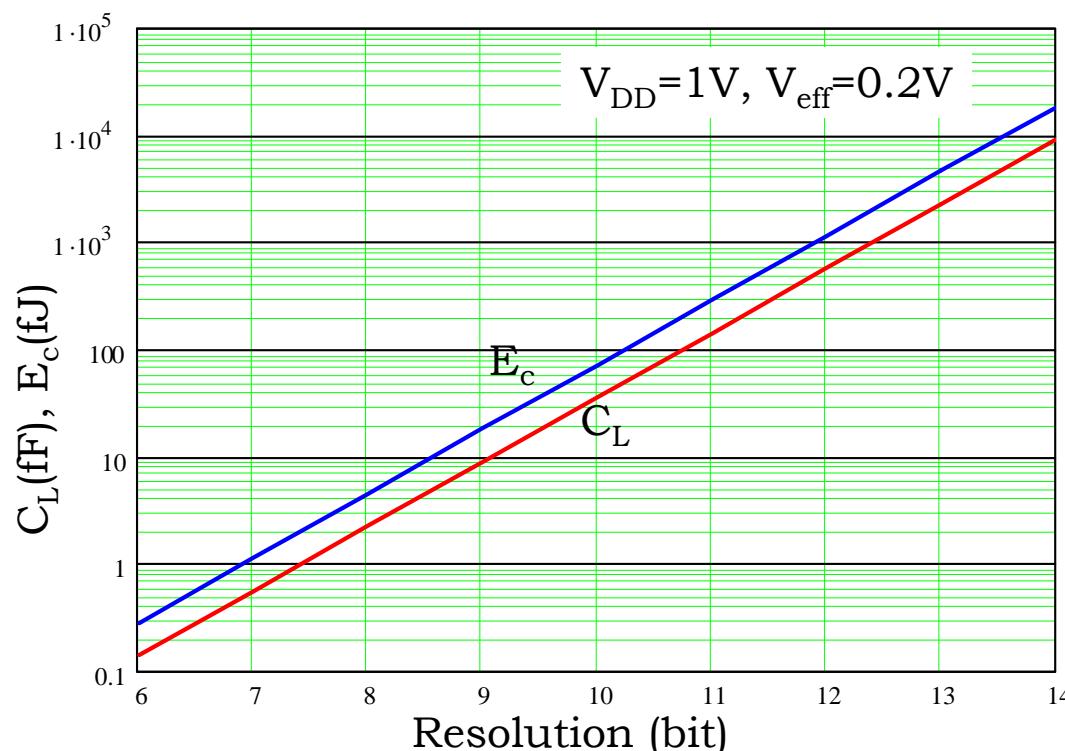
# Required capacitance and consumed Energy

23

Node capacitances should be increased to realize higher ADC resolution.  
This results in increase of consumed energy of the dynamic comparator.

Flash ADC:  $E_c$  determines the minimum FoM

SAR ADC:  $E_c$  cannot be neglected for higher resolution ADC



$E_c$ : conversion energy

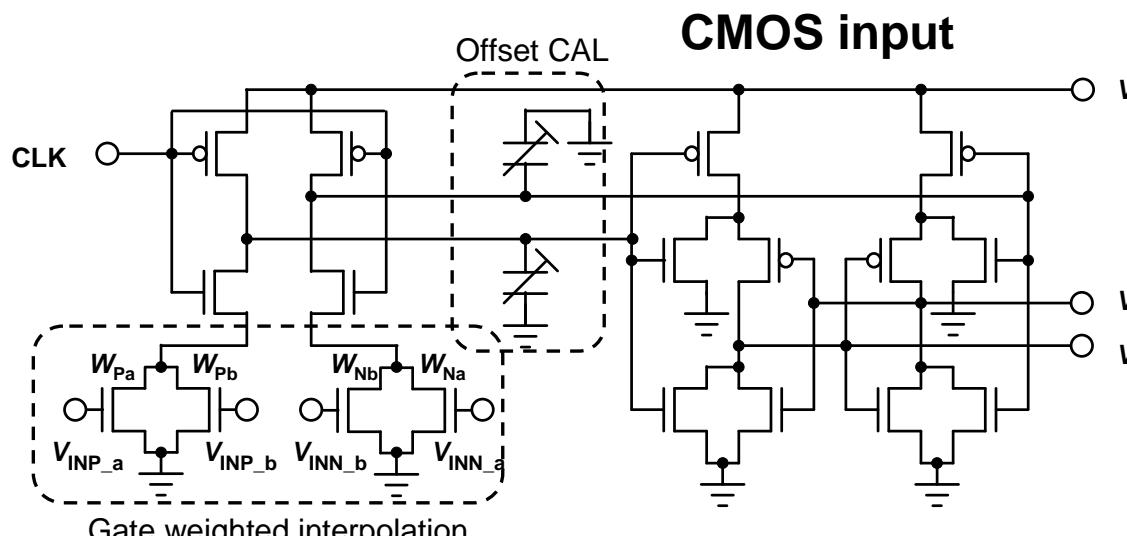
2fF & 4fJ @8bit  
40fF & 80fJ @10bit  
0.6pF & 1pJ @12bit  
10pF & 20pJ @14bit

# Noise improvement of dynamic comp.

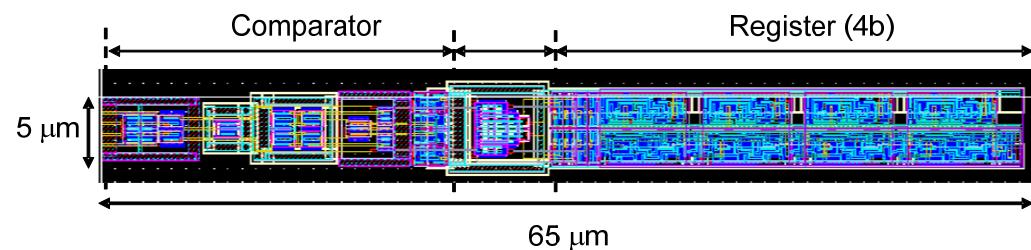
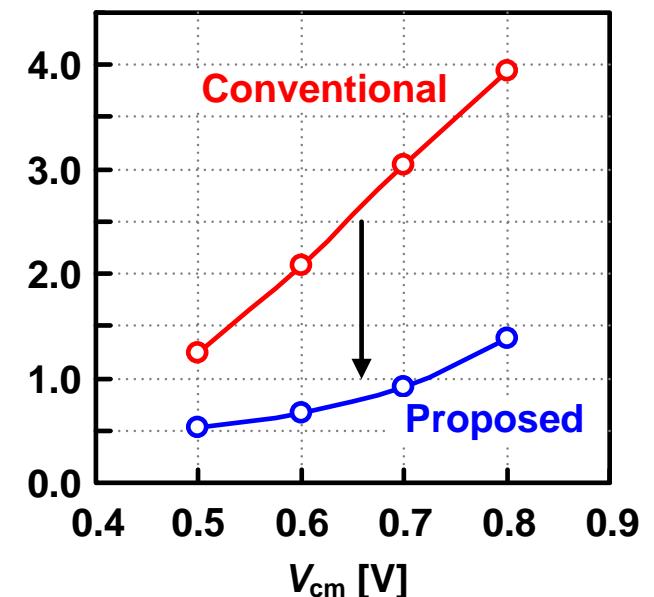
24

Noise of comparator can be reduced by complementary ckt. and an optimization of the node capacitance.

Dynamic comparator



Noise of comparator



A. Matsuzawa, Titech

2011.06.18

M. Miyahara, Y. Asada, D. Paik, and A. Matsuzawa,  
"A Low-Noise Self-Calibrating Dynamic Comparator  
for High-Speed ADCs," A-SSCC, Nov. 2008.

Yusuke Asada, Kei Yoshihara, Tatsuya Urano, Masaya  
Miyahara, and Akira Matsuzawa, "A 6bit, 7mW, 250fJ,  
700MS/s Subranging ADC," A-SSCC, 5-3, pp. 141-144,  
Taiwan, Taipei, Nov. 2009.

# P<sub>d</sub> estimation of SAR ADC

25

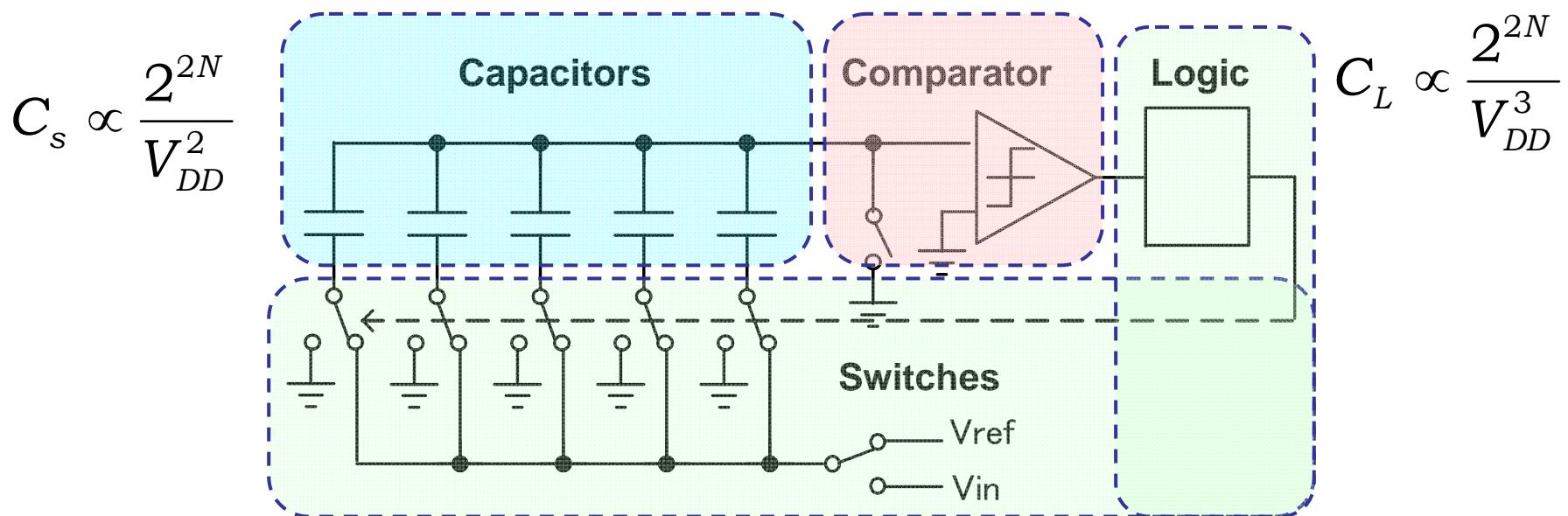
Divide SAR ADC into three different circuits.

## 1) S/H&CDAC

$$p_{ds} = 2f_c C_s V_{DD}^2$$

## 2) Comparator

$$p_{dc} = 2(N + 2)f_c C_L V_{DD}^2$$



2) Logic gates and switch drivers  $p_{dc} = 2Nf_c C_g V_{DD}^2$  **C<sub>g</sub>: const**

C<sub>s</sub>: Total sampling capacitance

C<sub>L</sub>: Load capacitance of comparator

C<sub>g</sub>: Effective capacitance of gates and switches

Akira Matsuzawa, ISSCC Forum, San Francisco, CA, Feb. 2011.

2011.06.18

A. Matsuzawa, Titech

# Equations to estimate the ADC performance

26

**Quantization voltage**  $\overline{V_q^2} = \frac{1}{3} \left( \frac{V_{DD}}{2^N} \right)^2$

**Permitted thermal noise**  $V_{n\_th}^2 = (2^{2\Delta ENOB} - 1) \overline{V_q^2}$     **Thermal Noise of COMP.**  $V_{n\_th}^2 = \frac{4kT}{C_L} \left( \gamma \frac{V_{DD}}{V_{eff}} + 1 \right) \left( \frac{V_{eff}}{V_{DD}} \right)^2$

**Sampling capacitor**  $C_s = \frac{4kT}{V_{n\_th}^2}$     **Load Capacitor Of COMP.**  $C_L = \frac{4kT}{V_{n\_th}^2} \left( \gamma \frac{V_{DD}}{V_{eff}} + 1 \right) \left( \frac{V_{eff}}{V_{DD}} \right)^2$

**P<sub>d</sub> of S/H**  $p_{ds} = 2f_c C_s V_{DD}^2$

**P<sub>d</sub> of COMP.**  $p_{dc} = 2(N+2)f_c C_L V_{DD}^2$      $FoM = \frac{(P_{ds} + P_{dc} + P_{dg}) \cdot 2^{\Delta ENOB}}{f_c \times 2^N}$

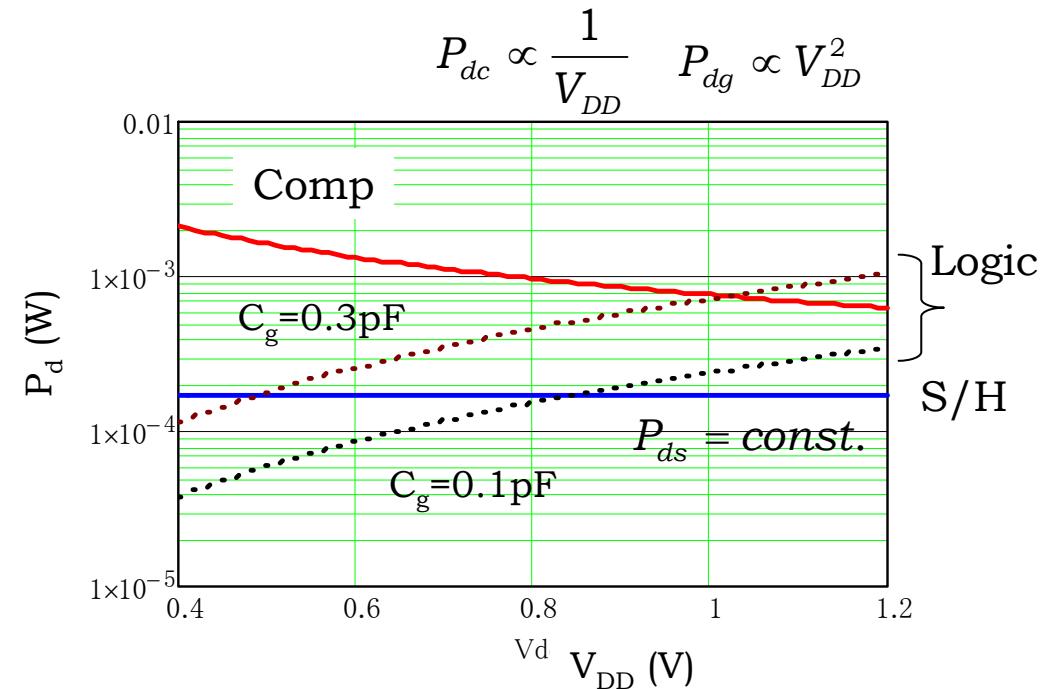
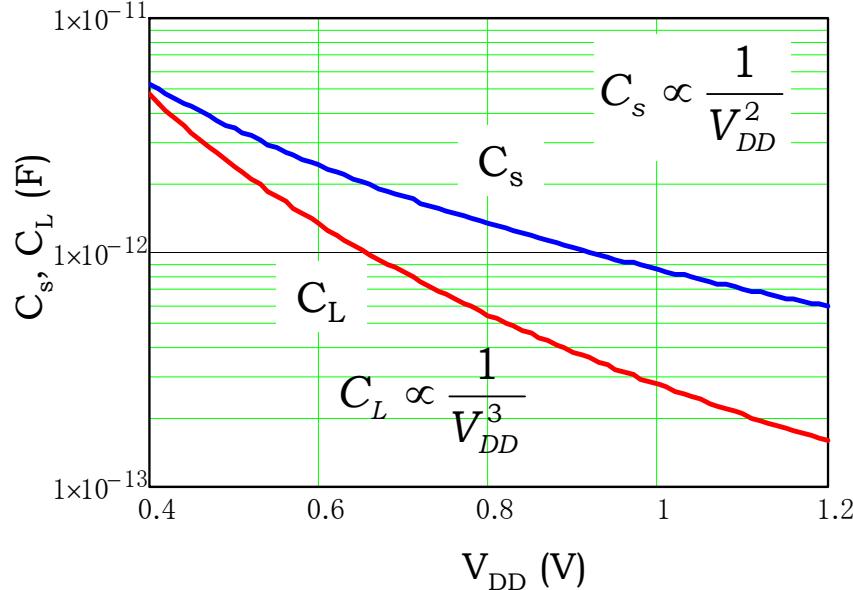
**P<sub>d</sub> of Gate**  $p_{dg} = 2Nf_c C_g V_{DD}^2$

# C, P<sub>d</sub>, and FoM vs. V<sub>DD</sub>

27

**Sampling capacitance C<sub>s</sub> and load capacitance C<sub>L</sub> increase with reducing V<sub>DD</sub>, since the quantization voltage decreases with reducing V<sub>DD</sub>.**

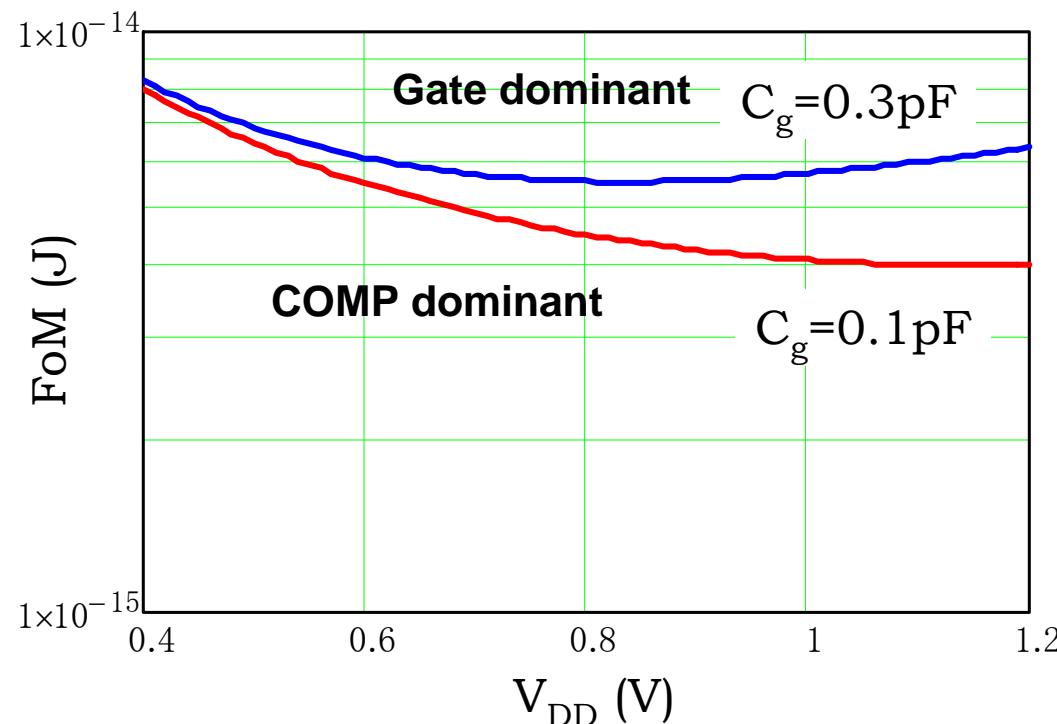
**P<sub>d</sub> of S/H is constant for V<sub>DD</sub>, however P<sub>d</sub> of comparator increases with reducing V<sub>DD</sub>. P<sub>d</sub> of logic gate decreases rapidly with reducing V<sub>DD</sub>.**



# FoM vs. $V_{DD}$

**FoM can be lowered by reducing  $V_{DD}$ , if  $P_d$  of logic gate is dominant.**

Thus the voltage lowering is effective to reduce  $P_d$  for low resolution ADC,  
However, it is still difficult to reduce  $P_d$  by reducing  $V_{DD}$  for high resolution ADC,  
even if SAR ADC architecture is used.



$$N = 12\text{bit}$$

$$F_c = 100\text{MHz}$$

$$\Delta ENOB = 0.5\text{bit}$$

$$\gamma = 2$$

$$T = 300^\circ K$$

$$V_{eff} = 0.15V$$

# Example: An ultra-low power CDC

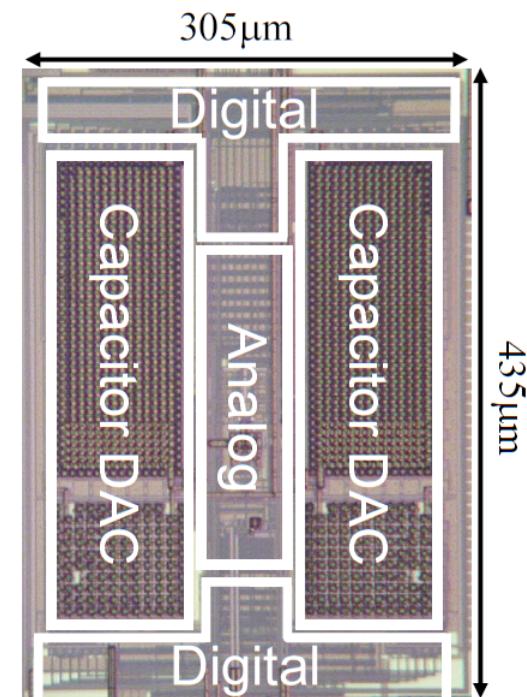
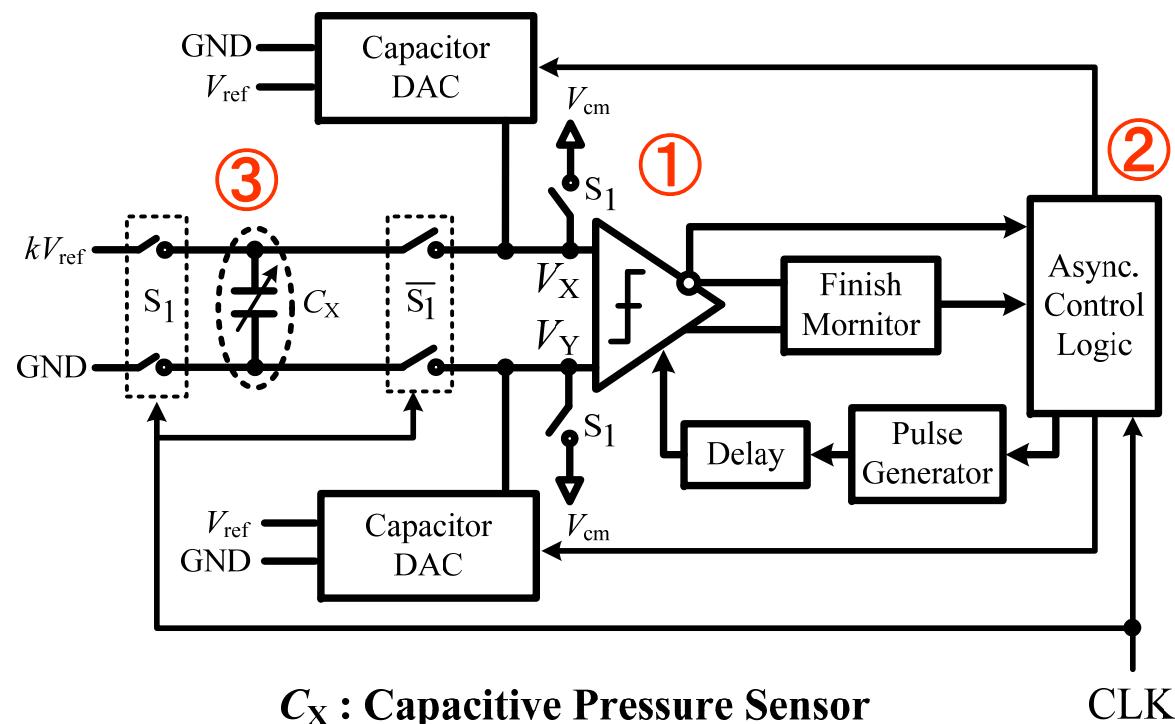
29

We have developed an ultra-low power Capacitance to Digital Converter.

1. 10b SAR like architecture
2. Self-clocking
3. Single to differential

**3nA @ 30 times/sec**

Tuan Minh Vo, Yasuhide Kuramochi, Masaya Miyahara, Takashi Kurashina, and Akira Matsuzawa  
"A 10-bit, 290 fJ/conv. Steps, 0.13mm<sup>2</sup>, Zero-Static Power, Self-Timed Capacitance to Digital Converter."  
SSDM 2009, OC<sup>-</sup>



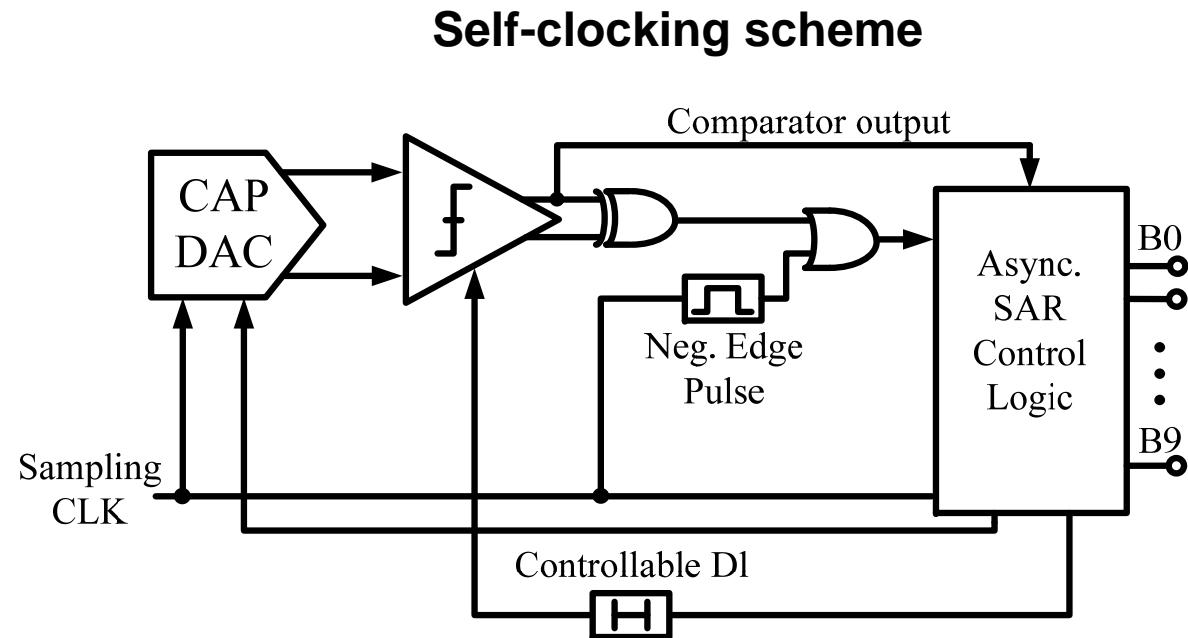
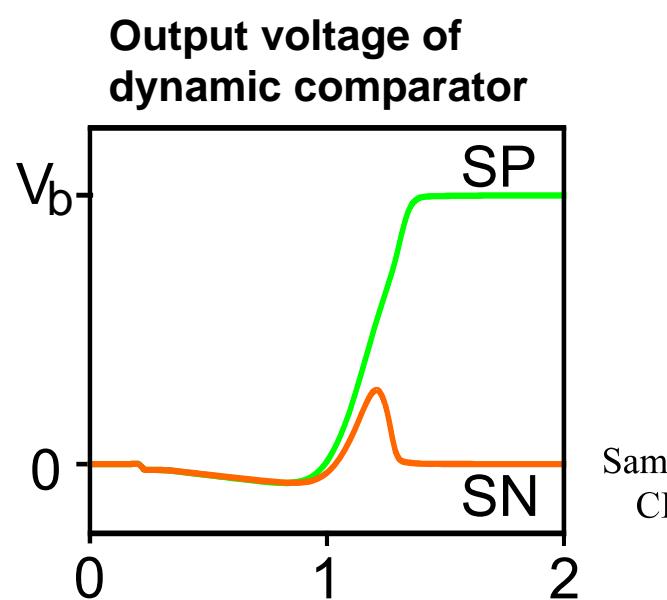
# Self clocking technique

30

Self-clocking scheme is very useful

- 1) Reducing power consumption (Clock circuits, routing clock, )
- 2) Just an enable command signal is required. No need of clock.  
Suitable for micro controller.

Comparison is ended if the output voltages are not same.



---

# Flash and sub-ranging ADCs

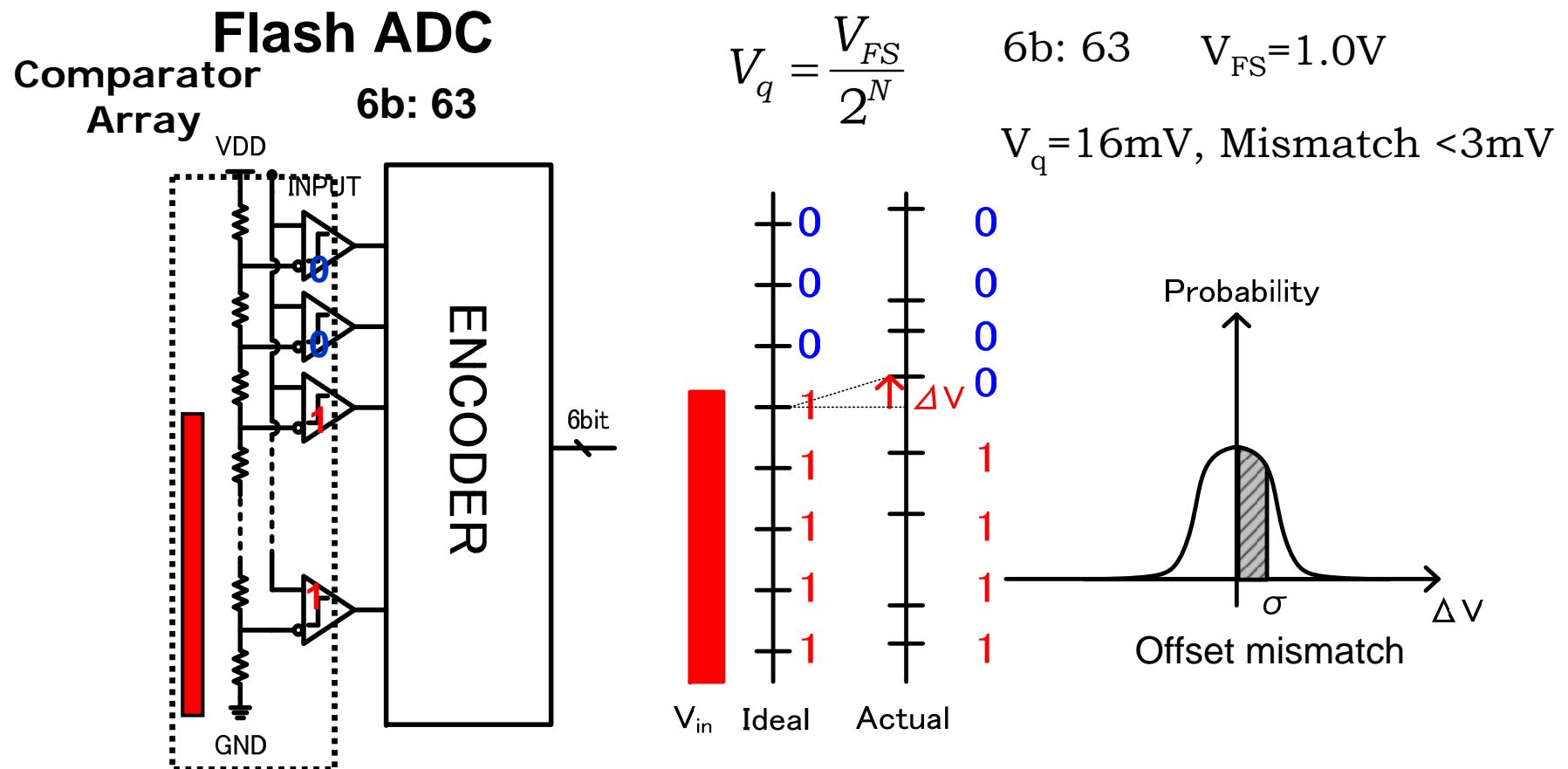
# Flash ADC

32

- Expecting highest speed
- Comparator determines the ADC performance

$$N \leq 6$$

Offset mismatch mainly determines the effective resolution.  
Thermal noise can be neglected because of low resolution.



# FoM of Flash ADC

33

**FoM of flash ADC is determined by energy consumption of unit comparator and the degradation of effective bit.**

**Reduction of consumed energy and increase of ENOB are very important.**

$$FoM = \frac{P_d}{f_s \times 2^{ENOB}} \approx \frac{E_c \cdot f_s \cdot 2^N}{f_s \times 2^{N-\Delta ENOB}} = E_c \cdot 2^{\Delta ENOB}$$

$$E_c = CV_{DD}^2 \quad E_c: \text{Energy/Comparator}$$

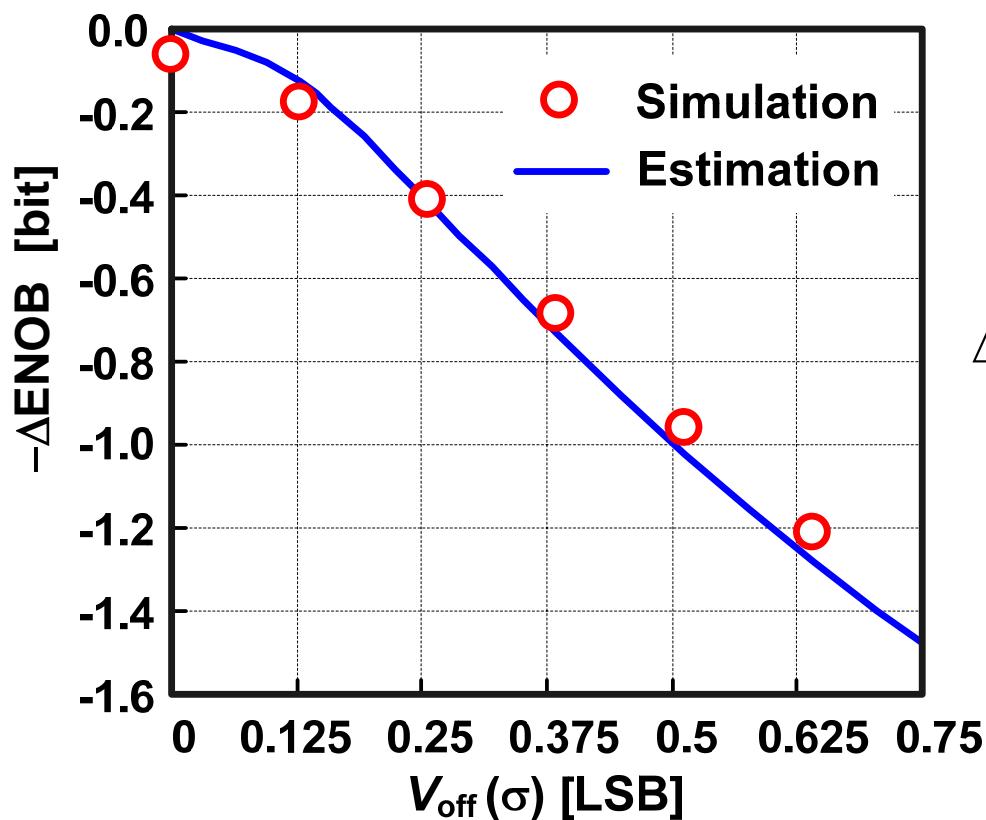
$$\Delta ENOB = \frac{1}{2} \log_2 \left[ 1 + 12 \left\{ \left( \frac{V_{off}(\sigma)}{V_q} \right)^2 + \left( \frac{V_n(\sigma)}{V_q} \right)^2 \right\} \right]$$

**Offset mismatch**      **Thermal noise (can be neglected)**

# Performance of flash ADC

34

FoM is degraded by the offset mismatch voltage of the comparator.  
Offset mismatch voltage should be reduced at low voltage operation.



$$\text{FoM} = \frac{P_d \cdot 2^{\Delta\text{ENOB}}}{f_c \times 2^N}$$

$$\Delta\text{ENOB} = \frac{1}{2} \log_2 \left( 1 + 12 \left( \frac{V_{\text{off}}(\sigma)}{V_q} \right)^2 \right)$$

$V_{\text{off}}(\sigma)$ : Offset mismatch

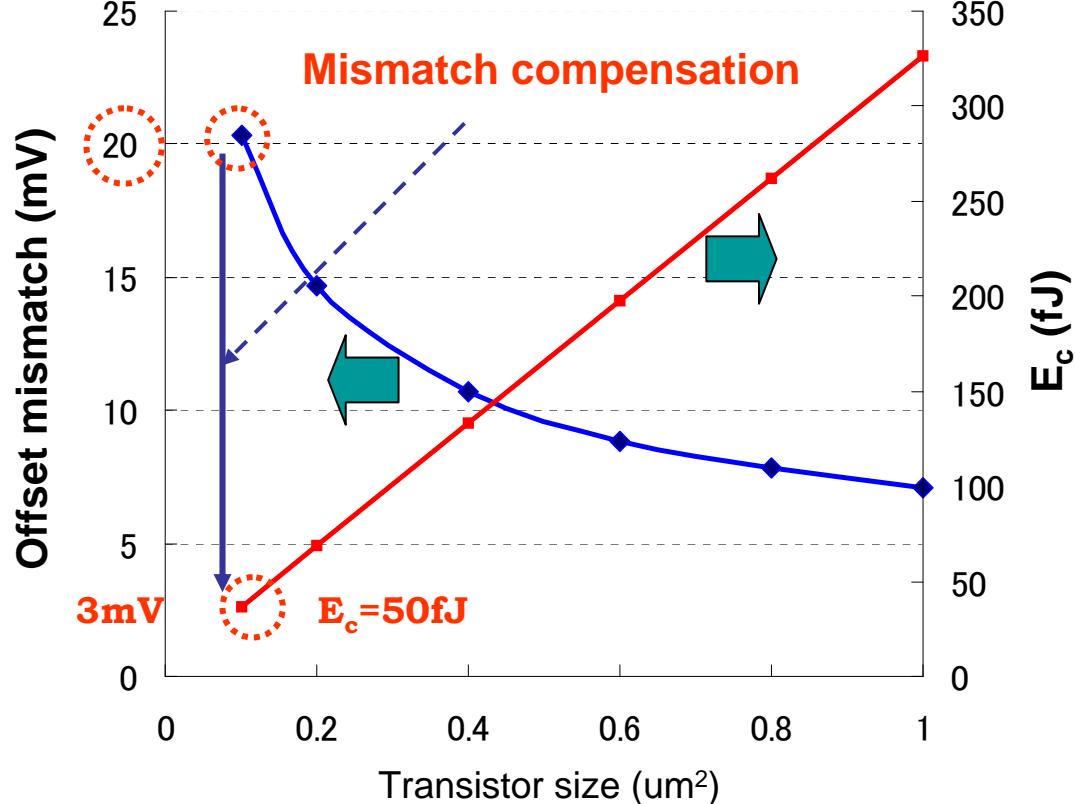
$V_q$  : 1 LSB voltage

# Tradeoff: mismatch and energy consumption

35

Serious tradeoff between mismatch of transistor and gate area.

Larger transistor is required to reduce mismatch voltage and results in increase of gate area and consumed energy.



## Example

6bit ADC:  $V_{\text{off}} < 3\text{mV}$   
 $E_c < 50\text{fJ} \rightarrow 0.1\text{um}^2 \rightarrow V_{\text{off}} = 20\text{mV}$   
Needs mismatch compensation  
 $20\text{mV} \rightarrow 3\text{mV}$

$$V_{\text{offset}}(\sigma) \propto \frac{1}{\sqrt{LW}}$$

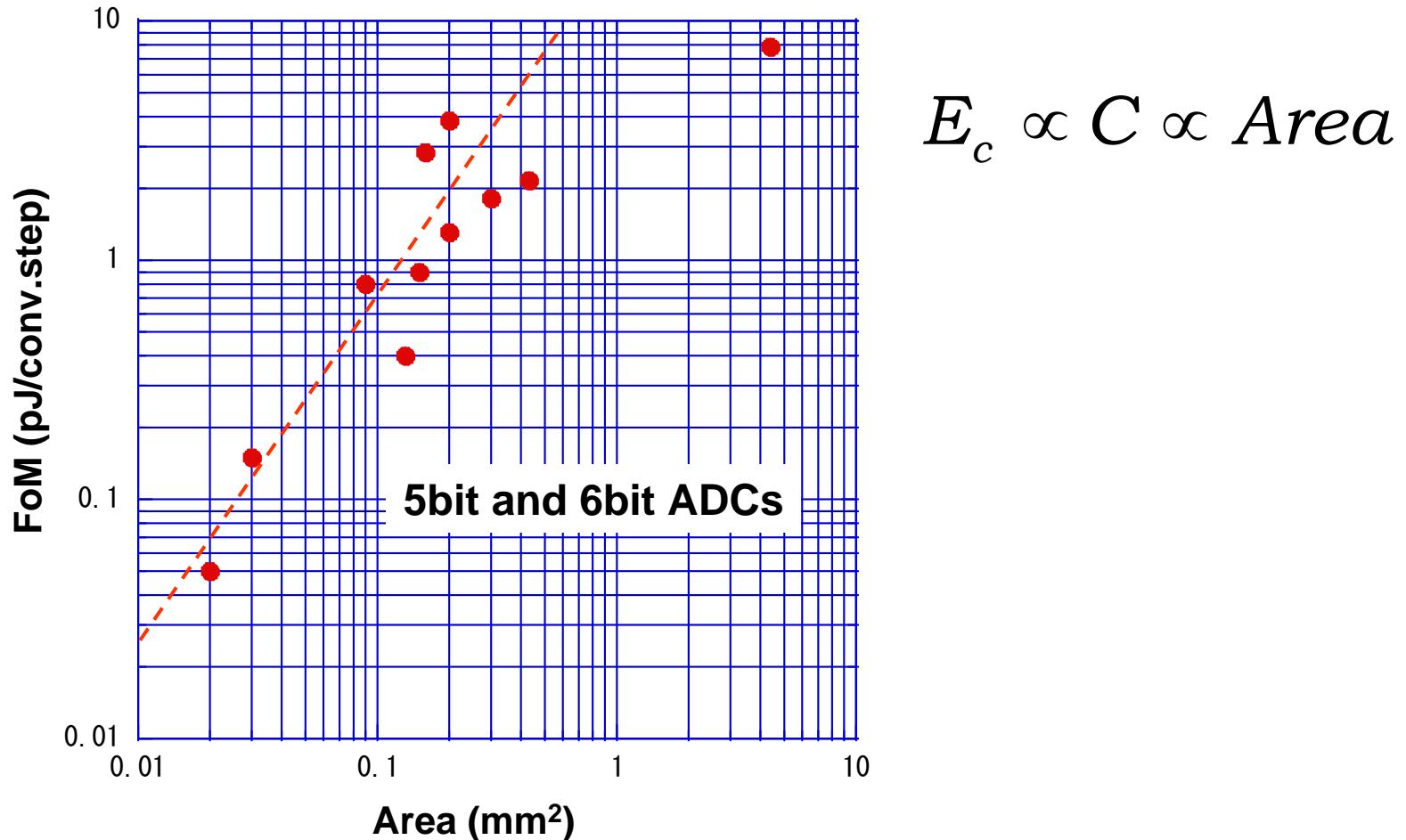
$$E_c \propto C_c \propto LW$$

$$E_c \propto \frac{1}{V_{\text{offset}}^2(\sigma)}$$

# FoM vs. Area

Occupied area should be reduced to lower the FoM.

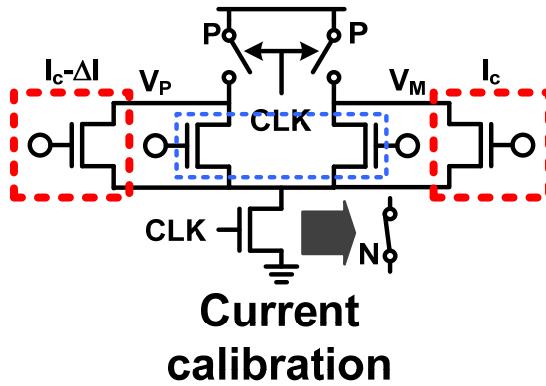
We must pay much attention to the occupied area.



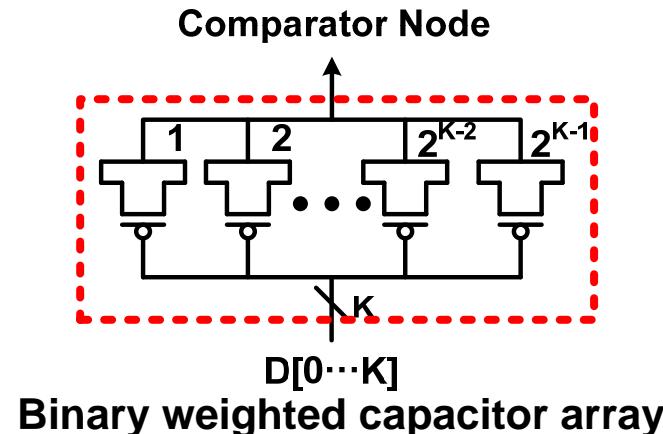
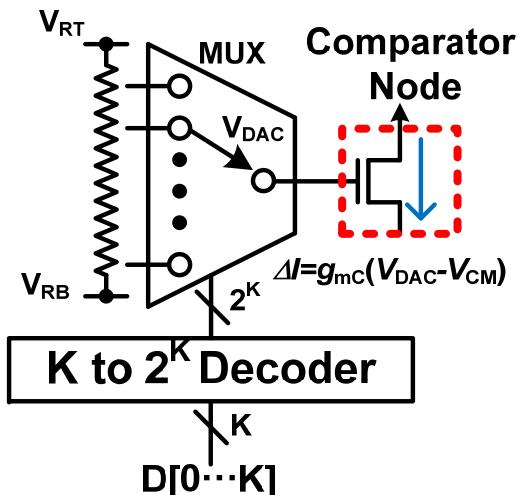
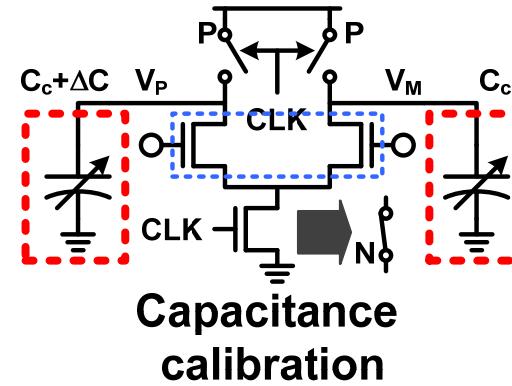
# Digital calibration methods for mismatch

37

Resistor ladder type



Capacitor array type



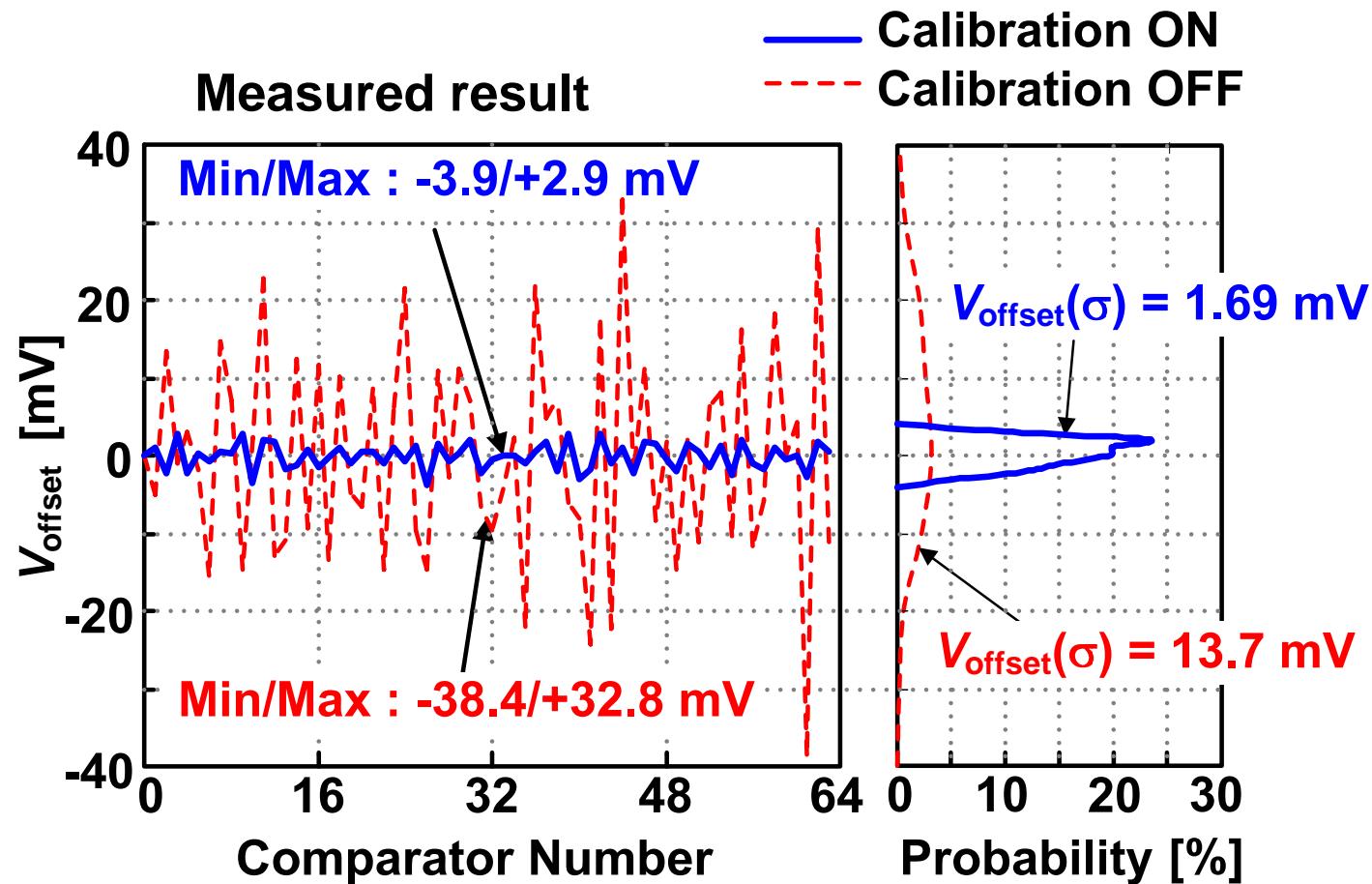
Y. Asada, K. Yoshihara, T. Urano, M. Miyahara and A. Matsuzawa,

"A 6bit, 7mW, 250fJ, 700MS/s Subranging ADC" A-SSCC, pp. 141-144, Nov. 2009.

# Effect of digital mismatch compensation

38

The mismatch voltage can be reduced from 14mV to 1.7mV.

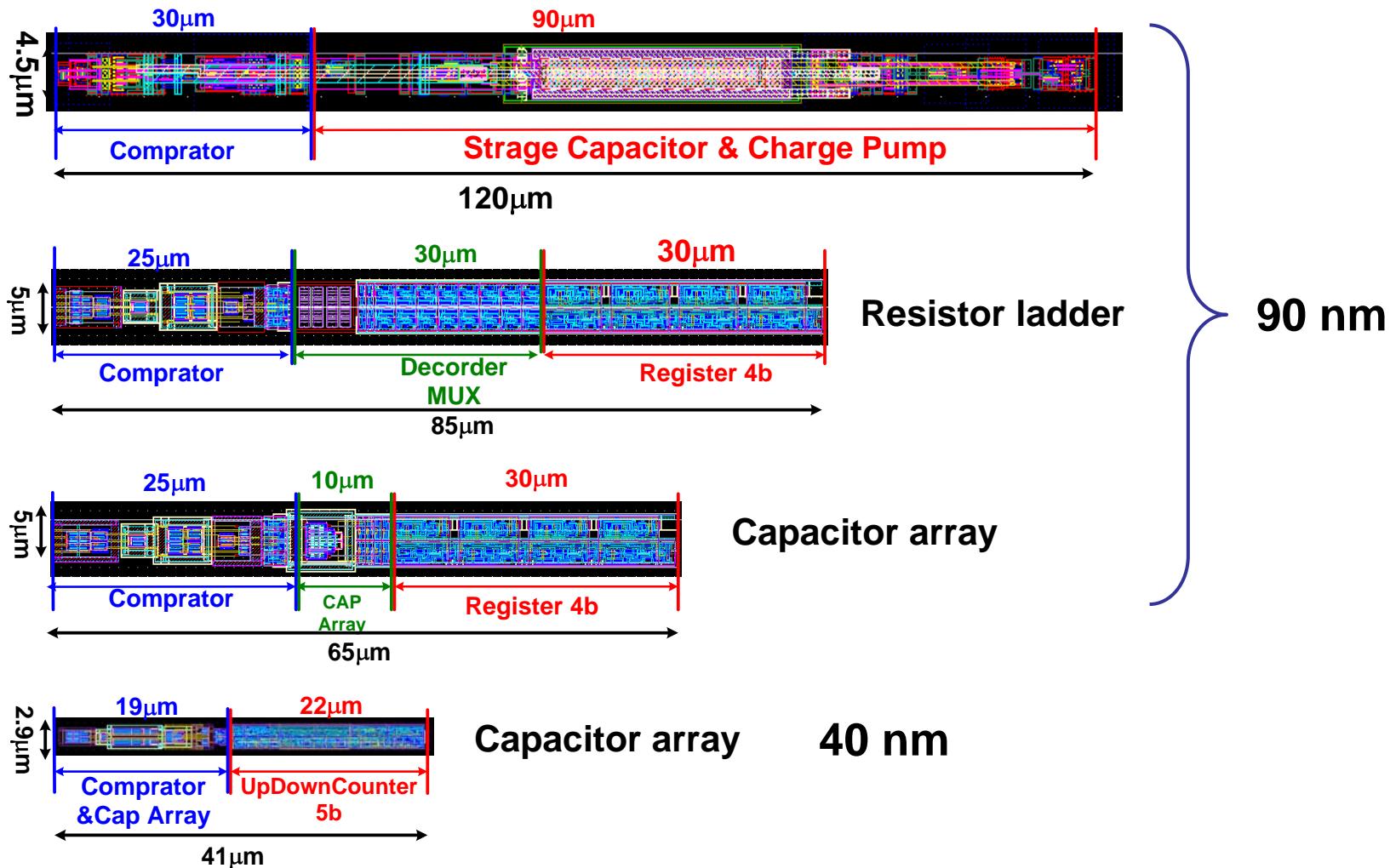


M. Miyahara, Y. Asada, D. Paik, and A. Matsuzawa, "A Low-Noise Self-Calibrating Dynamic Comparator for High-Speed ADCs," A-SSCC, Nov. 2008.

# Area comparison

39

Penalty area for digital compensation will be reduced with technology scaling.



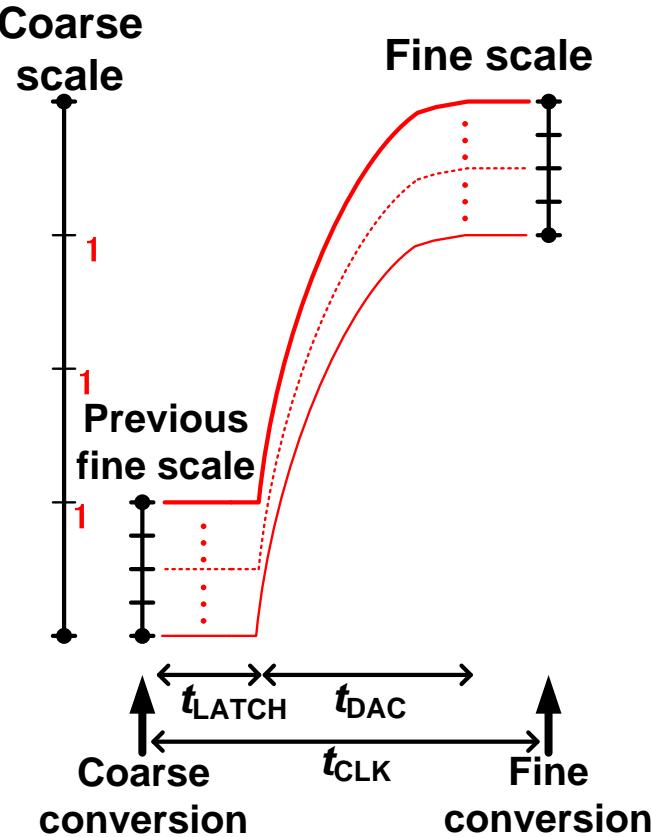
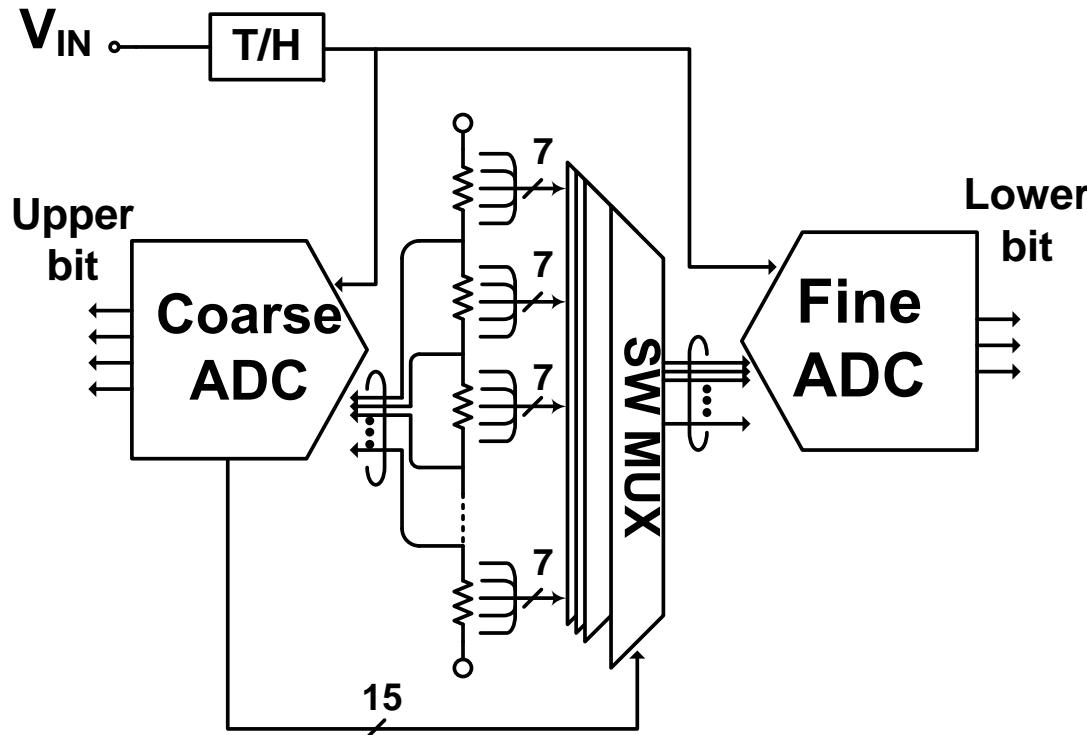
# Issue of resistor DAC to generate $V_{REF}$

40

Resistor DAC consumes static power and has a serious tradeoff between  $P_d$  and speed.

$$\tau_{ref\ max} \approx \left\{ \frac{R}{4} + R_{on} \right\} C_{pr} = \left\{ \frac{V_{ref}}{4I_{ref}} + R_{on} \right\} C_{pr}$$

$$\tau \propto \frac{1}{I}$$



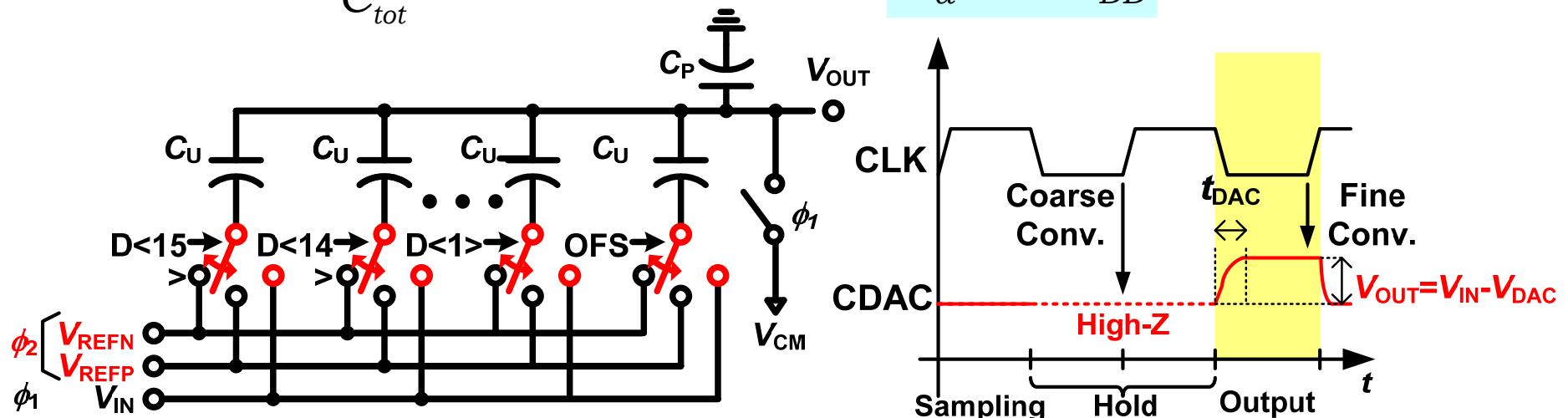
# Advantage of capacitor DAC to generate $V_{REF}$ <sup>41</sup>

Capacitor DAC doesn't consume static power and has no trade off between Pd and speed.

$$V_{out} = \frac{-1}{1 + \frac{C_p}{C_{tot}}} (V_{IN} - n \cdot V_{REF})$$

$$\tau \approx R_{on} C$$

$$E_d \approx CV_{DD}^2$$



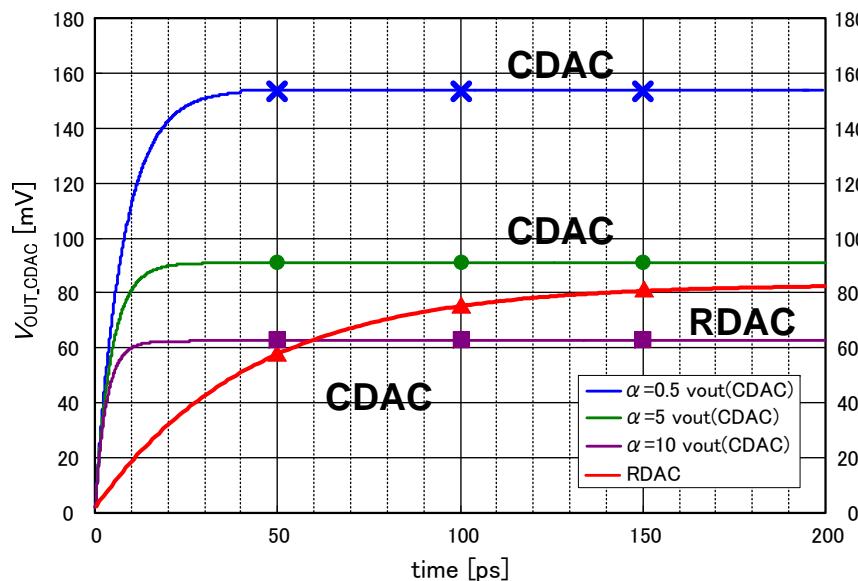
Operating as S/H circuit

- No static power consumption (  $360\mu\text{W}@1\text{GHz}$  )
- Smaller  $C_u$  realize faster settling time  
(  $t_{DAC} = 3.4 r_{on} C_u < 80\text{ps}$  @  $r_{ON} = 1\text{k}\Omega$ ,  $C_u = 15\text{fF}$  )

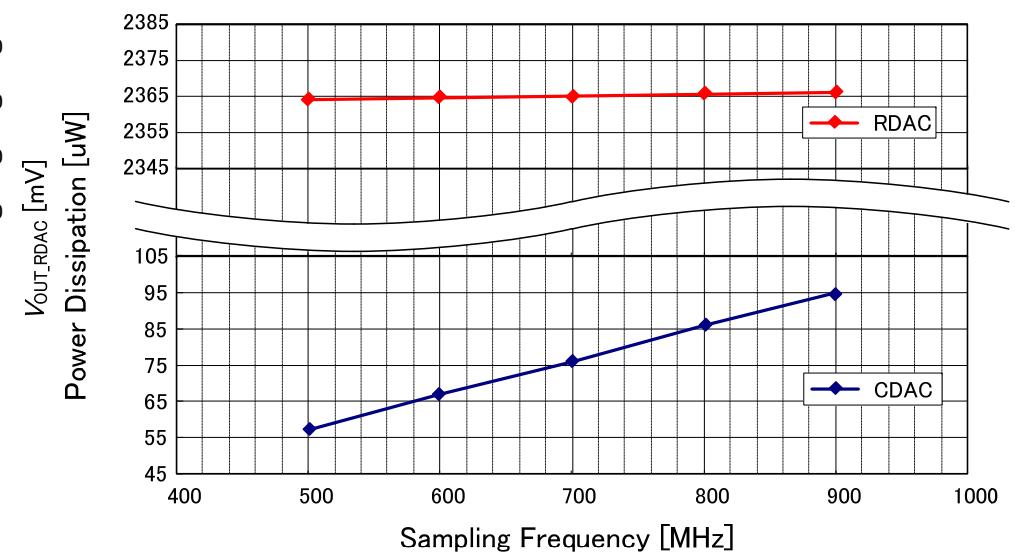
# Settling time and power

42

CDAC realizes faster settling time to RDAC with low power consumption.



Time response

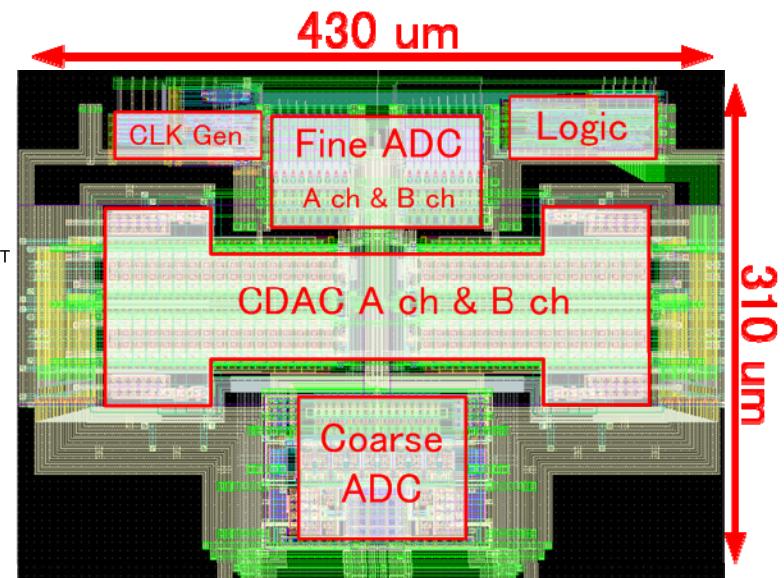
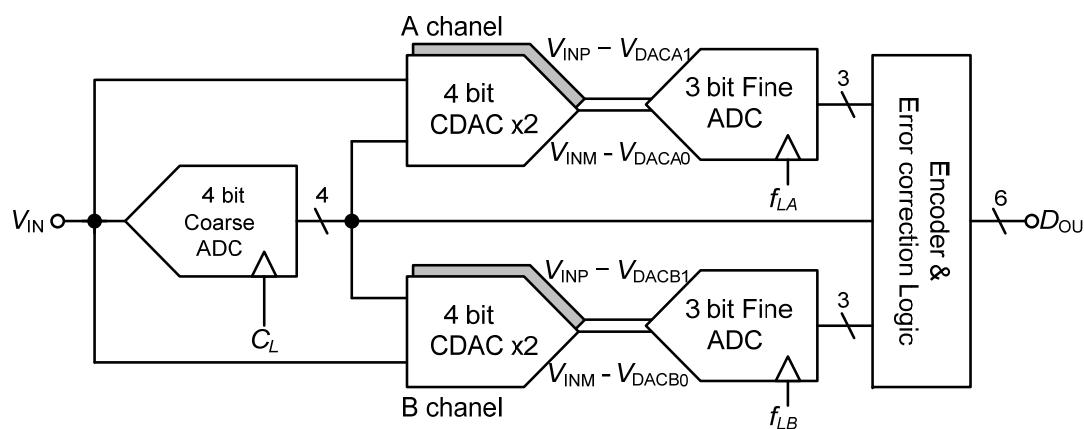


Power dissipation

# 6bit sub-ranging ADC using CDAC

43

6 bit ADC has been realized in a 90 nm 10M1P CMOS technology with a chip area of 0.13mm<sup>2</sup>



Y. Asada, K. Yoshihara, T. Urano, M. Miyahara and A. Matsuzawa,  
“A 6bit, 7mW, 250fJ, 700MS/s Subranging ADC” A-SSCC, pp. 141-144, Nov. 2009.

# Performance comparison

44

Attain lowest FoM at that time

	[1]	[2]	[3]	[4]	[6]	This Work
Resolution(bit)	6	6	6	6	6	6
fs(GS/s)	0.8	1.2	0.7	1.25	1	0.7
SNDR(DC/Nyq.)	35/32	34/33	31/30	34/28	35/33	35/34
Pd (mW)	12	75	24	32	30	7
Active area(mm <sup>2</sup> )	0.13	0.43	0.052	0.09	0.18	0.13
VDD(V)	1.2	1.2	1.2	1.2	1.2/1.0	1.2
FoM(pJ)	0.44	2.17	1.31	1.22	0.8	0.25
CMOS Tech.(nm)	65	130	130	130	90	90
Architecture	Flash	Flash	Pipeline	2b-SAR	Subrange	Subrange

[1] C-Y. Chen, VLSI Circuits 2008.

[2] B-W. Chen, A-SSCC 2008.

[3] F. C. Hsieh, A-SSCC 2008.

[4] Z. Cao, ISSCC 2008.

[6] Y. C. Lien, A-SSCC 2008.

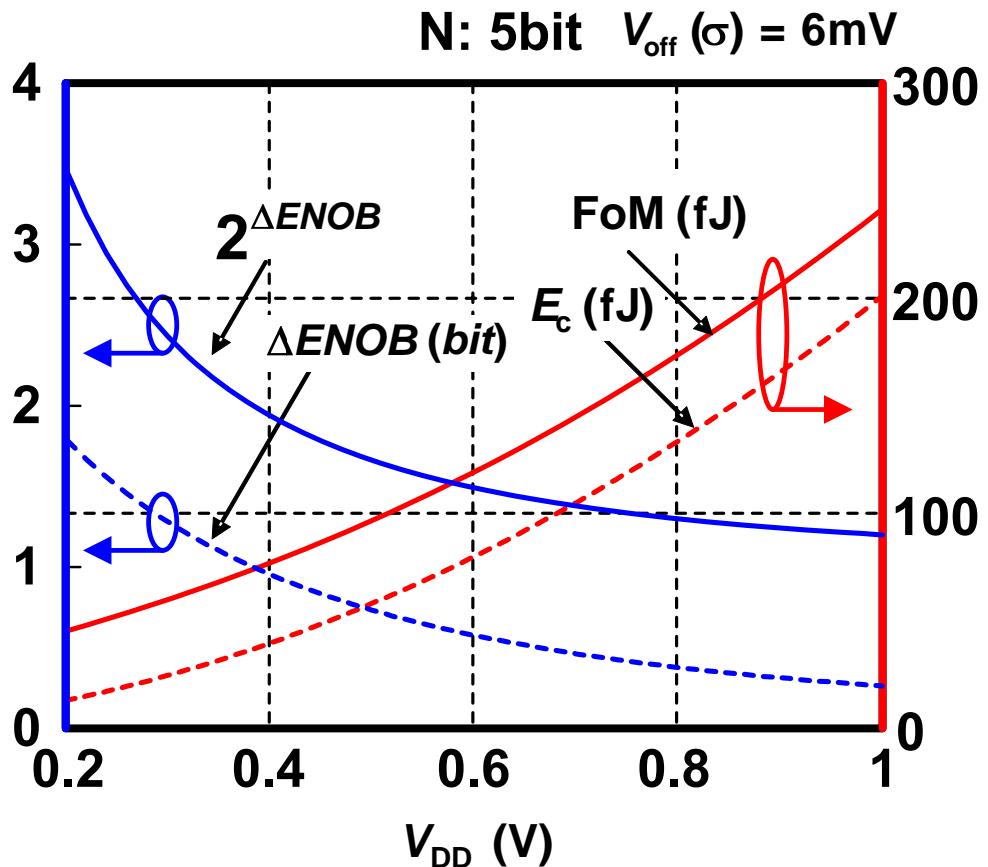
# Voltage lowering: FoM vs. $V_{DD}$

45

FoM can be reduced drastically by reducing supply voltage  $V_{DD}$ .

ENOB is degraded by the reduction of  $V_{DD}$ , however little affects the FoM.

Energy reduction by reducing  $V_{DD}$  is dominant.



$$\Delta ENOB = \frac{1}{2} \log_2 \left( 1 + 12 \left( \frac{V_{off}(\sigma)}{V_q} \right)^2 \right)$$

$$E_c = C_c V_{DD}^2 + \frac{V_{DD} \cdot I_c \exp\left(-\frac{V_T}{S}\right)}{f_c}$$

$$\text{FoM} \approx E_c \cdot 2^{\Delta ENOB}$$

$E_c$ :Energy consumption for each comparator and followed logic circuits.

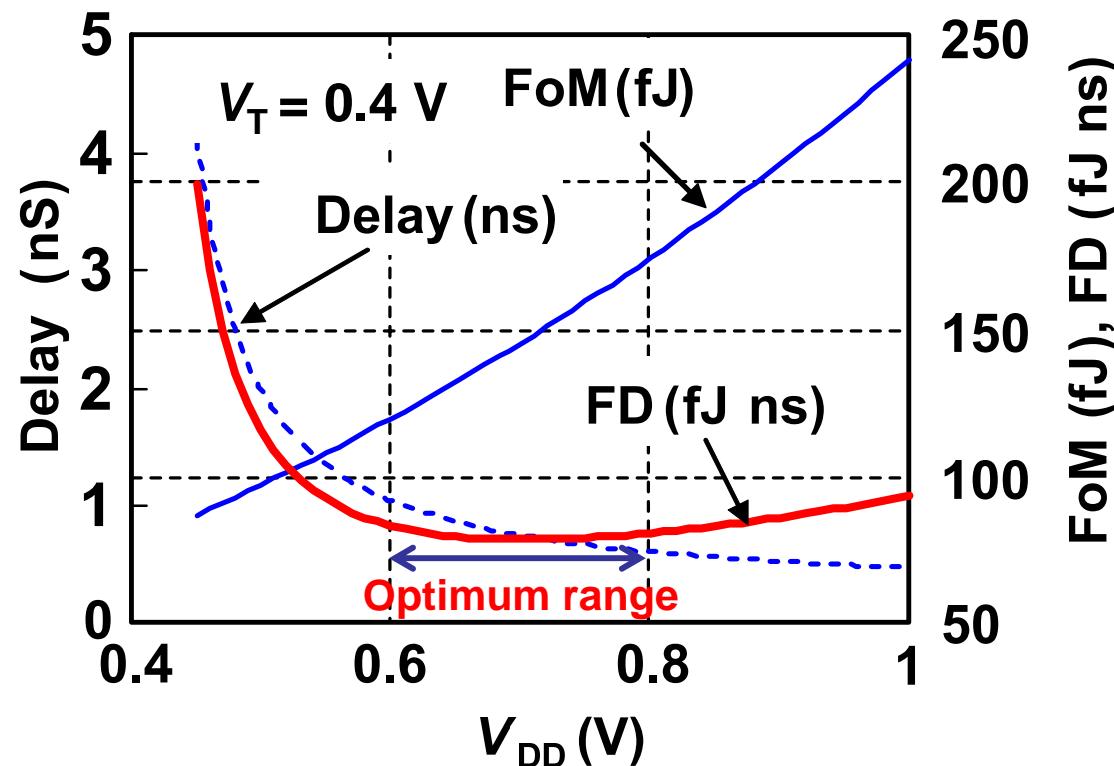
# FoM delay (FD) product

46

The FD product suggests the balance between the number of interleaving and decrease of energy consumption.

Delay is increased and the operating speed is lowered by reducing  $V_{DD}$

We should investigate the optimum  $V_{DD}$  by FD product.



$$FD = FoM \times Delay$$

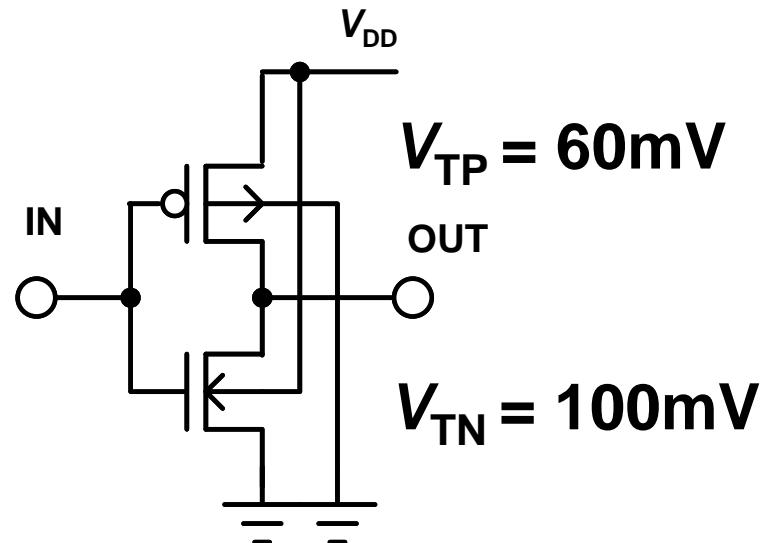
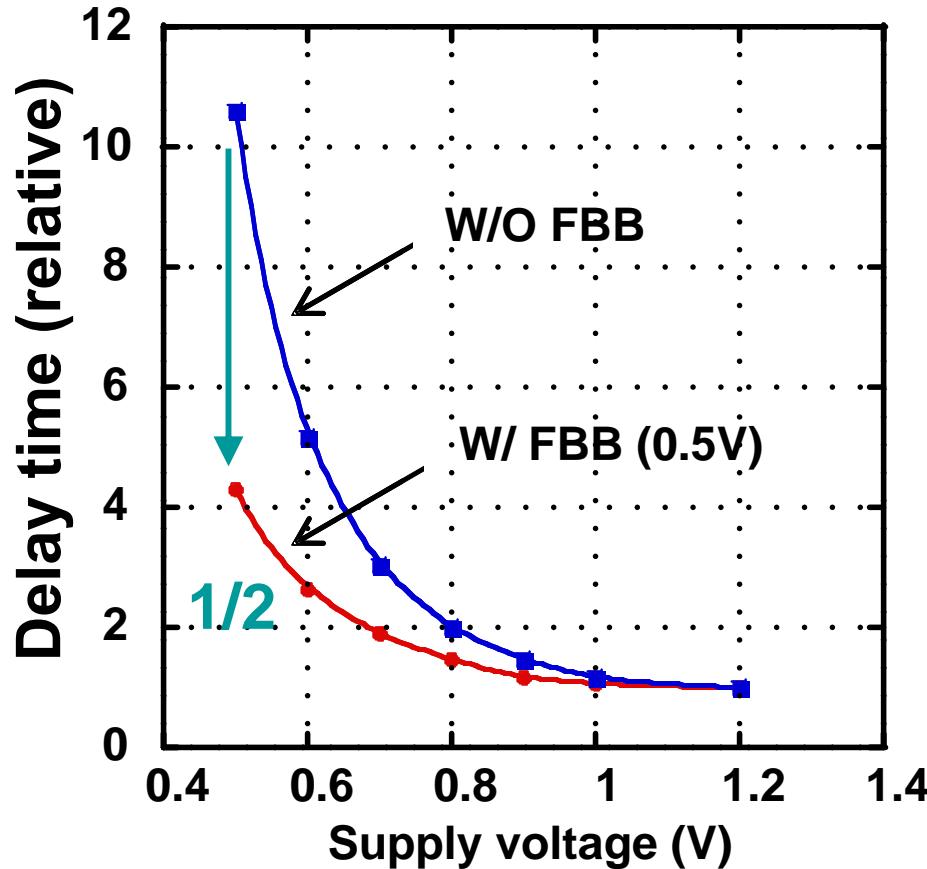
Delay time

$$T_d = k \frac{V_{DD}}{(V_{DD} - V_T)^\alpha}$$

# Forward body biasing

47

Forward body biasing can decrease the delay time (1/2) and can be used easily at 0.5 V operation.



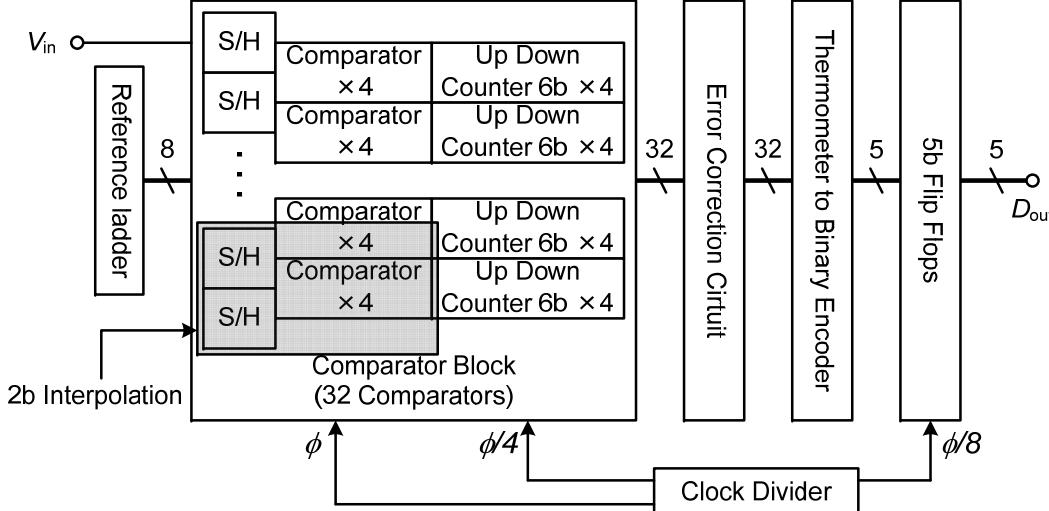
Increased leakage current in the proposed ADC is 0.32 mA by forward body biasing.

# ADC Structure

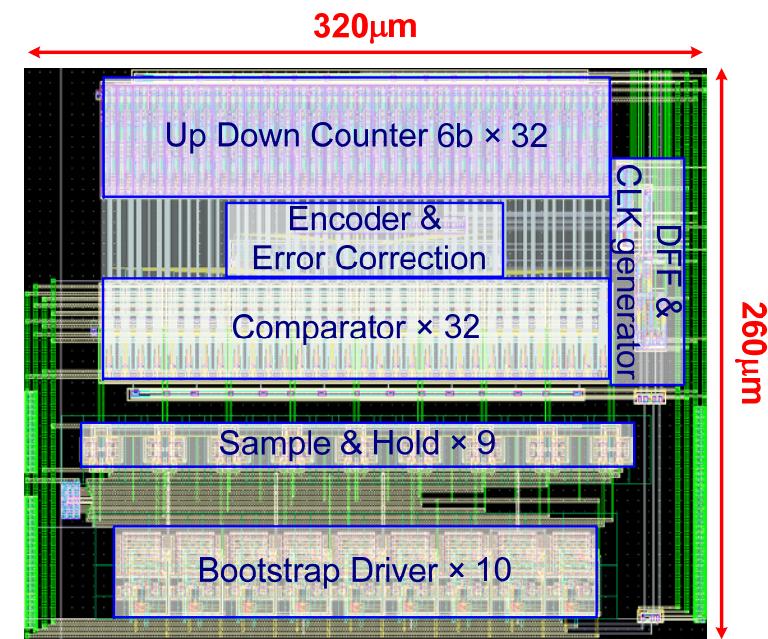
48

5bit 0.5V 600MSps Flash ADC is designed and fabricated in 90nm CMOS.

S/H circuits use gate boosted switches.



Block diagram of ADC



Chip microphotograph

M. Miyahara , J. Lin, K. Yoshihara, and A. Matsuzawa,  
“A 0.5 V, 1.2mW, 160fJ, 600 MS/s 5 bit Flash ADC”  
A-SSCC, pp. 177-180, Nov. 2010.

# Performance Summary

49

A high speed and low FoM 0.5V flash ADC has been realized.

Reference #	[7]	[8]	[9]	[10]	This work
Resolution (bit)	5	5	5	5	5
fs (GS/s)	0.5	1.75	1.75	0.06	0.6
SNDR (dB)	26	30	30	26	27
Pd (mW)	5.9	2.2	7.6	1.3	1.2
Active area (mm <sup>2</sup> )	0.87	0.017	0.03	-	0.083
Vdd (V)	1.2	1	1	0.6	0.5
FoM(fJ)	750	50	150	1060	160
CMOS Tech. (nm)	65	90	90	90	90
Architecture	SAR	Fold+Flash	Flash	Flash	Flash

$$\text{FoM}_{\text{Fmax}} = 160 \text{fJ} @ 600 \text{MSps}$$

$$\text{FoM}_{\text{Best}} = 110 \text{ fJ} @ 360 \text{MSps}$$

[7] B. P. Ginsburg, J. Solid-State Circuits 2007.

[8] B. Verbruggen, ISSCC 2008.

[9] B. Verbruggen, VLSI Circuits 2008.

[10] J. E. Proesel, CICC 2008.

## Reducing static power

Resistor DAC → Capacitor DAC

OpAmp based → Comparator based

## Reducing capacitance

$$E_d \approx CV_{DD}^2$$

# of CMP Flash → Sub-range → SAR

$$\Delta V_T \propto \frac{1}{\sqrt{C_G}}$$

TR size Large TR → Small TR with compensation

$$\overline{V_n} \propto \frac{1}{\sqrt{C}}$$

Noise Use complementally ckt.

Clock Use self clocking

## Reducing voltage

Effective to digital gates and low resolution ADC

Use forward or adaptive body biasing